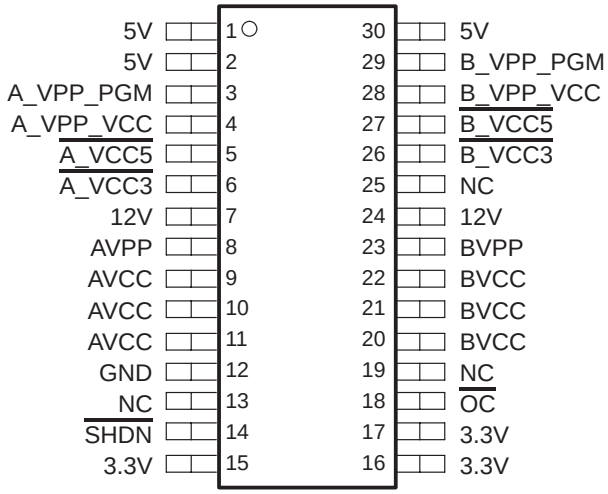
- **Fully Integrated $V_{CC}$ and $V_{pp}$ Switching for Dual-Slot PC Card™ Interface**
- **Compatible With Controllers From Cirrus, Ricoh, $O_2$Micro, Intel, and Texas Instruments**
- **3.3-V Low-Voltage Mode**
- **Meets PC Card Standards**
- **12-V Supply Can Be Disabled Except During 12-V Flash Programming**
- **Short Circuit and Thermal Protection**
- **30-Pin SSOP (DB) and 32-Pin TSSOP (DAP)**
- **Compatible With 3.3-V, 5-V and 12-V PC Cards**
- **Low $r_{DS(on)}$ (140-mΩ 5-V $V_{CC}$ Switch; 110-mΩ 3.3-V $V_{CC}$ Switch)**
- **Break-Before-Make Switching**

**DB OR DF PACKAGE**
**(TOP VIEW)**

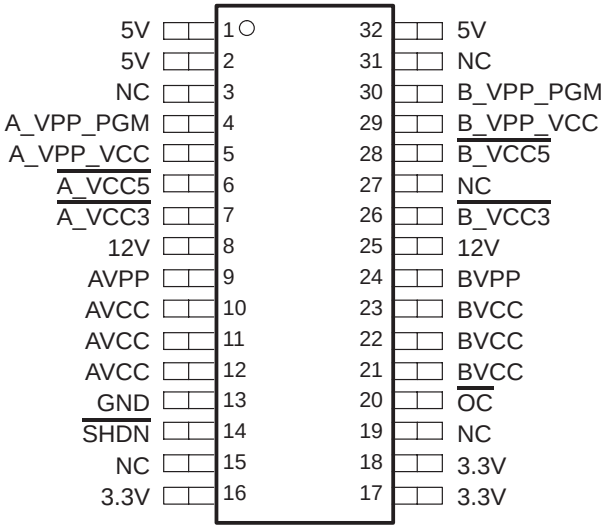



## description

The TPS2205 PC Card power-interface switch provides an integrated power-management solution for two PC Cards. All of the discrete power MOSFETs, a logic section, current limiting, and thermal protection for PC Card control are combined on a single integrated circuit (IC), using the Texas Instruments LinBiCMOS™ process. The circuit allows the distribution of 3.3-V, 5-V, and/or 12-V card power, and is compatible with many PCMCIA controllers. The current-limiting feature eliminates the need for fuses, which reduces component count and improves reliability.

The TPS2205 is backward compatible with the TPS2201, except that there is no $V_{DD}$ connection. Bias current is derived from either the 3.3-V input pin or the 5-V input pin. The TPS2205 also eliminates the APWR_GOOD and BPWR_GOOD pins of the TPS2201.

**DAP PACKAGE**
**(TOP VIEW)**




NC − No internal connection

The TPS2205 features a 3.3-V low-voltage mode that allows for 3.3-V switching without the need for 5 V. This facilitates low-power system designs such as sleep mode and pager mode where only 3.3 V is available.

End equipment for the TPS2205 includes notebook computers, desktop computers, personal digital assistants (PDAs), digital cameras, and bar-code scanners.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

LinBiCMOS is a trademark of Texas Instruments.
PC Card is a trademark of PCMCIA (Personal Computer Memory Card International Association).

**PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.**

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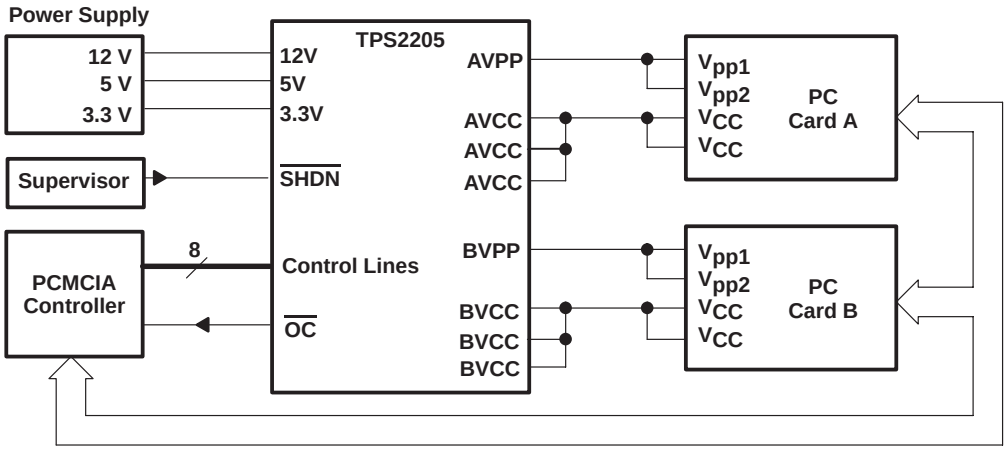
**AVAILABLE OPTIONS**

| $T_A$ | PACKAGED DEVICES | | | CHIP FORM (Y) |
|---|---|---|---|---|
| | PLASTIC SMALL OUTLINE (DB) | PLASTIC SMALL OUTLINE (DF) | TSSOP (DAP) | |
| −40°C to 85°C | TPS2205IDBR | TPS2205IDFR | TPS2205IDAPR | TPS2205Y |

The DB, DF, and DAP packages are only available taped and reeled, indicated by the R suffix on the device type.

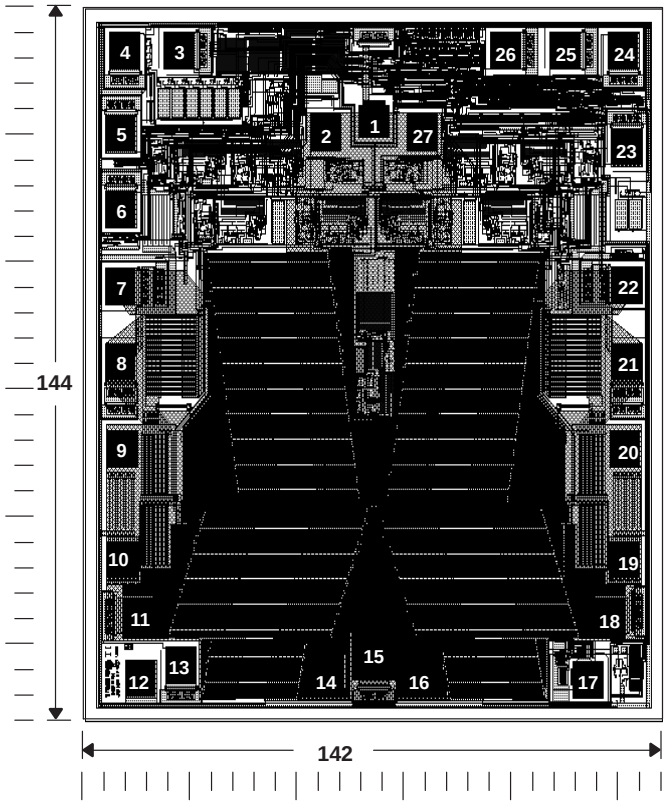
## typical PC card power-distribution application

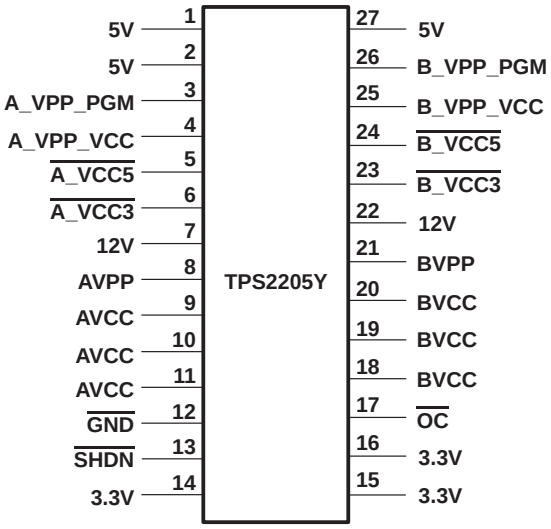


## TPS2205Y chip information

This chip, when properly assembled, displays characteristics similar to those of the TPS2205. Thermal compression or ultrasonic bonding may be used on the doped-aluminum bonding pads. The chips may be mounted with conductive epoxy or a gold-silicon preform.

**BONDING PAD ASSIGNMENTS**




**CHIP THICKNESS: 15 TYPICAL**

**BONDING PADS: 4 × 4 MINIMUM**

**$T_J$ max = 150°C**

**TOLERANCES ARE ±10%.**

**ALL DIMENSIONS ARE IN MILS.**

## Terminal Functions

| TERMINAL | | | I/O | DESCRIPTION |
|---|---|---|---|---|
| NAME | NO. | | | |
| | DB, DF | DAP | | |
| $\overline{\text{A_VCC3}}$ | 6 | 7 | I | Logic input that controls voltage on AVCC (see TPS2205 Control-Logic table) |
| $\overline{\text{A_VCC5}}$ | 5 | 6 | I | Logic input that controls voltage on AVCC (see TPS2205 Control-Logic table) |
| A_VPP_PGM | 3 | 4 | I | Logic input that controls voltage on AVPP (see TPS2205 Control-Logic table) |
| A_VPP_VCC | 4 | 5 | I | Logic input that controls voltage on AVPP (see TPS2205 Control-Logic table) |
| AVCC | 9, 10, 11 | 10, 11, 12 | O | Switched output that delivers 0 V, 3.3 V, 5 V, or high impedance |
| AVPP | 8 | 9 | O | Switched output that delivers 0 V, 3.3 V, 5 V, 12 V, or high impedance |
| $\overline{\text{B_VCC3}}$ | 26 | 26 | I | Logic input that controls voltage on BVCC (see TPS2205 Control-Logic table) |
| $\overline{\text{B_VCC5}}$ | 27 | 28 | I | Logic input that controls voltage on BVCC (see TPS2205 Control-Logic table) |
| B_VPP_PGM | 29 | 30 | I | Logic input that controls voltage on BVPP (see TPS2205 Control-Logic table) |
| B_VPP_VCC | 28 | 29 | I | Logic input that controls voltage on BVPP (see TPS2205 Control-Logic table) |
| BVCC | 20, 21, 22 | 21, 22, 23 | O | Switched output that delivers 0 V, 3.3 V, 5 V, or high impedance |
| BVPP | 23 | 24 | O | Switched output that delivers 0 V, 3.3 V, 5 V, 12 V, or high impedance |
| $\overline{\text{SHDN}}$ | 14 | 14 | I | Logic input that shuts down the TPS2205 and set all power outputs to high-impedance state |
| $\overline{\text{OC}}$ | 18 | 20 | O | Logic-level overcurrent reporting output that goes low when an overcurrent condition exists |
| GND | 12 | 13 | | Ground |
| 3.3V | 15, 16, 17 | 16, 17, 18 | I | 3.3-V $V_{CC}$ in for card power |
| 5V | 1, 2, 30 | 1, 2, 32 | I | 5-V $V_{CC}$ in for card power |
| 12V | 7, 24 | 8, 25 | I | 12-V VPP in for card power |
| NC | 13, 19, 25 | 3, 15, 19, 27, 31 | I | No internal connection |

### absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Input voltage range for card power: $V_{I(5V)}$ . . . . . −0.3 V to 7 V
$V_{I(3.3V)}$ . . . . . −0.3 V to 7 V
$V_{I(12V)}$ . . . . . −0.3 V to 14 V
Logic input voltage . . . . . −0.3 V to 7 V
Continuous total power dissipation . . . . . See Dissipation Rating Table
Output current (each card): $I_{O(xVCC)}$ . . . . . Internally limited
$I_{O(xVPP)}$ . . . . . Internally limited
Operating virtual junction temperature range, $T_J$ . . . . . −40°C to 150°C
Operating free-air temperature range, $T_A$ . . . . . −40°C to 85°C
Storage temperature range, $T_{stg}$ . . . . . −55°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

**DISSIPATION RATING TABLE**

| PACKAGE | | $T_A \le 25°C$ POWER RATING | DERATING FACTOR‡ ABOVE $T_A = 25°C$ | $T_A = 70°C$ POWER RATING | $T_A = 85°C$ POWER RATING |
|---|---|---|---|---|---|
| DB | | 1024 mW | 8.2 mW/°C | 655 mW | 532 mW |
| DF | | 1158 mW | 9.26 mW/°C | 741 mW | 602 mW |
| DAP | No backplane | 1625 mW | 13 mW/°C | 1040 mW | 845 mW |
| | Backplane§ | 6044 mW | 48.36 mW/°C | 3869 mW | 3143 mW |

‡ These devices are mounted on an FR4 board with no special thermal considerations.
§ 2-oz backplane with 2-oz traces; 5.2-mm × 11-mm thermal pad with 6-mil solder; 0.18-mm diameter vias in a 3×6 array.

## recommended operating conditions

| | | MIN | MAX | UNIT |
|---|---|---|---|---|
| Input voltage range, $V_I$ | $V_{I(5V)}$ | 0 | 5.25 | V |
| | $V_{I(3.3V)}$ | 0 | 5.25 | V |
| | $V_{I(12V)}$ | 0 | 13.5 | V |
| Output current | $I_{O(xVCC)}$ at 25°C | | 1 | A |
| | $I_{O(xVPP)}$ at 25°C | | 150 | mA |
| Operating virtual junction temperature, $T_J$ | | −40 | 125 | °C |

## electrical characteristics, $T_A = 25°C$, $V_{I(5V)} = 5$ V (unless otherwise noted)

### dc characteristics

| PARAMETER | | | TEST CONDITIONS | | TPS2205 MIN | TPS2205 TYP | TPS2205 MAX | UNIT |
|---|---|---|---|---|---|---|---|---|
| | Switch resistances† | 5 V to xVCC | | | | 103 | 140 | mΩ |
| | | 3.3 V to xVCC | $V_{I(5V)}$ = 5 V, | $V_{I(3.3\ V)}$ = 3.3 V | | 69 | 110 | mΩ |
| | | 3.3 V to xVCC | $V_{I(5V)}$ = 0, | $V_{I(3.3V)}$ = 3.3 V | | 96 | 180 | mΩ |
| | | 5 V to xVPP | | | | | 6 | Ω |
| | | 3.3 V to xVPP | | | | | 6 | Ω |
| | | 12 V to xVPP | | | | | 1 | Ω |
| $V_{O(xVPP)}$ | Clamp low voltage | | $I_{pp}$ at 10 mA | | | | 0.8 | V |
| $V_{O(xVCC)}$ | Clamp low voltage | | $I_{CC}$ at 10 mA | | | | 0.8 | V |
| $I_{lkg}$ | Leakage current | $I_{pp}$ high-impedance state | $T_A = 25°C$ | | | 1 | 10 | µA |
| | | | $T_A = 85°C$ | | | | 50 | µA |
| | | $I_{CC}$ high-impedance state | $T_A = 25°C$ | | | 1 | 10 | µA |
| | | | $T_A = 85°C$ | | | | 50 | µA |
| $I_I$ | Input current | $V_{I(5V)}$ = 5 V | $V_{O(AVCC)} = V_{O(BVCC)}$ = 5 V, $V_{O(AVPP)} = V_{O(BVPP)}$ = 12 V | | | 117 | 150 | µA |
| | | $V_{I(5V)}$ = 0, $V_{I(3.3V)}$ = 3.3 V | $V_{O(AVCC)} = V_{O(BVCC)}$ = 3.3 V, $V_{O(AVPP)} = V_{O(BVPP)}$ = 0 | | | 131 | 150 | µA |
| | | Shutdown mode | $V_{O(BVCC)} = V_{O(AVCC)} = V_{O(AVPP)} = V_{O(BVPP)}$ = Hi-Z | | | | 1 | µA |
| $I_{OS}$ | Short-circuit output-current limit | $I_{O(xVCC)}$ | $T_J = 85°C$, Output powered up into a short to GND | | 1 | | 2.2 | A |
| | | $I_{O(xVPP)}$ | | | 120 | | 400 | mA |

† Pulse-testing techniques are used to maintain junction temperature close to ambient temperature; thermal effects must be taken into account separately.

## electrical characteristics, $T_A$ = 25°C, $V_{I(5V)}$ = 5 V (unless otherwise noted)

### logic section

| PARAMETER | TEST CONDITIONS | TPS2205 MIN | TPS2205 MAX | UNIT |
|---|---|---|---|---|
| Logic input current | | | 1 | μA |
| Logic input high level | | 2 | | V |
| Logic input low level | | | 0.8 | V |
| Logic output high level | $V_{I(5V)}$= 5 V, $I_O$ = 1mA | $V_{I(5V)}$−0.4 | | V |
| | $V_{I(5V)}$= 0 V, $V_{I(3.3V)}$ = 3.3 V, $I_O$ = 1mA, | $V_{I(3.3V)}$−0.4 | | |
| Logic output low level | $I_O$ = 1mA | | 0.4 | V |

### switching characteristics†‡

| PARAMETER | | TEST CONDITIONS | | TPS2205 MIN | TPS2205 TYP | TPS2205 MAX | UNIT |
|---|---|---|---|---|---|---|---|
| $t_r$ | Output rise time | $V_{O(xVCC)}$ | | | 1.2 | | ms |
| | | $V_{O(xVPP)}$ | | | 5 | | |
| $t_f$ | Output fall time | $V_{O(xVCC)}$ | | | 10 | | |
| | | $V_{O(xVPP)}$ | | | 14 | | |
| $t_{pd}$ | Propagation delay (see Figure 1) | $V_{I(x_VPP_PGM)}$ to $V_{O(xVPP)}$ | $t_{on}$ | | 4.4 | | ms |
| | | | $t_{off}$ | | 18 | | ms |
| | | $V_{I(\overline{x_VCC5})}$ to xVCC (3.3 V), $V_{I(5V)}$ = 5 V | $t_{on}$ | | 6.5 | | ms |
| | | | $t_{off}$ | | 20 | | ms |
| | | $V_{I(\overline{x_VCC5})}$ to xVCC (5 V) | $t_{on}$ | | 5.7 | | ms |
| | | | $t_{off}$ | | 25 | | ms |
| | | $V_{I(\overline{x_VCC5})}$ to xVCC (3.3 V), $V_{I(5V)}$ = 0 | $t_{on}$ | | 6.6 | | ms |
| | | | $t_{off}$ | | 21 | | ms |

† Refer to Parameter Measurement Information
‡ Switching Characteristics are with $C_L$ = 150 μF.

## electrical characteristics, $T_A$ = 25°C, $V_{I(5V)}$ = 5 V (unless otherwise noted)

### dc characteristics

| PARAMETER | | TEST CONDITIONS | | TPS2205Y MIN | TPS2205Y TYP | TPS2205Y MAX | UNIT |
|---|---|---|---|---|---|---|---|
| Switch resistances§ | 5 V to xVCC | | | | 103 | | mΩ |
| | 3.3 V to xVCC | $V_{I(5V)}$ = 5 V, | $V_{I(3.3\ V)}$ = 3.3 V | | 69 | | mΩ |
| | 3.3 V to xVCC | $V_{I(5V)}$ = 0, | $V_{I(3.3V)}$ = 3.3 V | | 96 | | mΩ |
| | 5 V to xVPP | | | | 4.74 | | Ω |
| | 3.3 V to xVPP | | | | 4.74 | | Ω |
| | 12 V to xVPP | | | | 0.724 | | Ω |
| $V_{O(xVPP)}$ Clamp low voltage | | $I_{pp}$ at 10 mA | | | 0.275 | | V |
| $V_{O(xVCC)}$ Clamp low voltage | | $I_{CC}$ at 10 mA | | | 0.275 | | V |
| $I_{lkg}$ Leakage current | $I_{pp}$ High-impedance state | $T_A$ = 25°C | | | 1 | | μA |
| | $I_{CC}$ High-impedance state | $T_A$ = 25°C | | | 1 | | μA |
| $I_I$ Input current | $V_{I(5V)}$ = 5 V | $V_{O(AVCC)}$ = $V_{O(BVCC)}$ = 5 V, $V_{O(AVPP)}$ = $V_{O(BVPP)}$ = 12 V | | | 117 | | μA |
| | $V_{I(5V)}$ = 0, $V_{I(3.3V)}$ = 3.3 V | $V_{O(AVCC)}$ = $V_{O(BVCC)}$ = 3.3 V, $V_{O(AVPP)}$ = $V_{O(BVPP)}$ = 0 | | | 131 | | μA |

§ Pulse-testing techniques are used to maintain junction temperature close to ambient temperature; thermal effects must be taken into account separately.

### switching characteristics†‡

| PARAMETER | | TEST CONDITIONS | | TPS2205Y MIN | TPS2205Y TYP | TPS2205Y MAX | UNIT |
|---|---|---|---|---|---|---|---|
| $t_r$ Output rise time | | $V_{O(xVCC)}$ | | | 1.2 | | ms |
| | | $V_{O(xVPP)}$ | | | 5 | | ms |
| $t_f$ Output fall time | | $V_{O(xVCC)}$ | | | 10 | | ms |
| | | $V_{O(xVPP)}$ | | | 14 | | ms |
| $t_{pd}$ Propagation delay (see Figure 1) | | $V_{I(x_VPP_PGM)}$ to $V_{O(xVPP)}$ | $t_{on}$ | | 4.4 | | ms |
| | | | $t_{off}$ | | 18 | | ms |
| | | $V_{I(x_VCC5)}$ to xVCC (3.3 V), $V_{I(5V)}$ = 5 V | $t_{on}$ | | 6.5 | | ms |
| | | | $t_{off}$ | | 20 | | ms |
| | | $V_{I(x_VCC5)}$ to xVCC (5 V) | $t_{on}$ | | 5.7 | | ms |
| | | | $t_{off}$ | | 25 | | ms |
| | | $V_{I(x_VCC5)}$ to xVCC (3.3 V), $V_{I(5V)}$ = 0 | $t_{on}$ | | 6.6 | | ms |
| | | | $t_{off}$ | | 21 | | ms |

† Refer to Parameter Measurement Information
‡ Switching Characteristics are with $C_L$ = 150 μF.

## PARAMETER MEASUREMENT INFORMATION

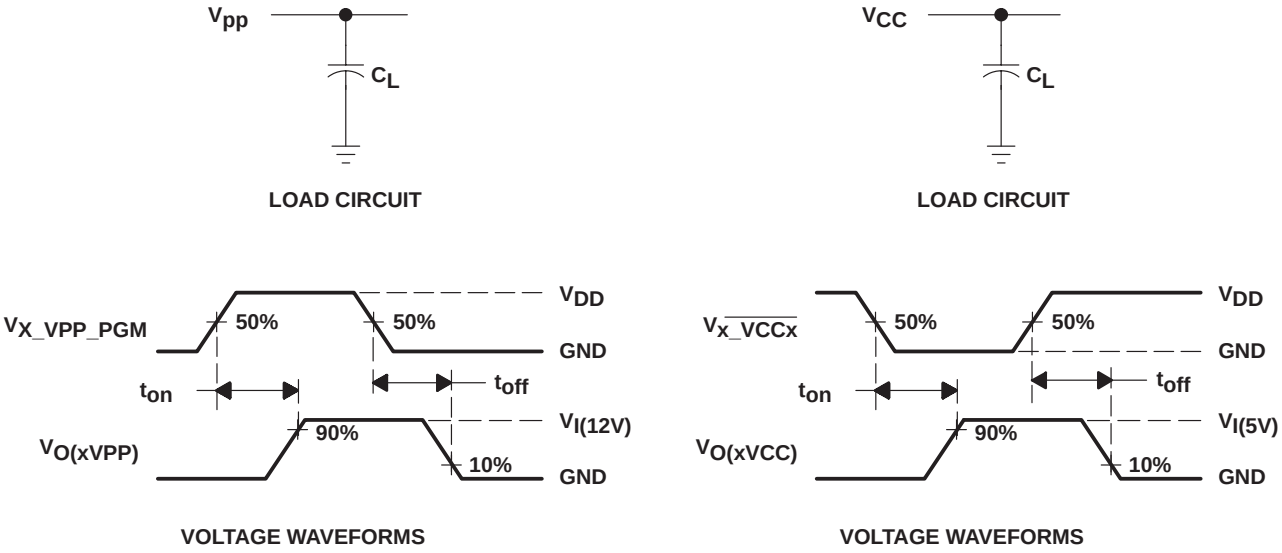



**Figure 1. Test Circuits and Voltage Waveforms**

### Table of Timing Diagrams

| | FIGURE |
|---|---|
| xVCC Propagation Delay and Rise Time With 1-µF Load, 3.3-V Switch, $V_{I(5V)}$ = 5 V | 2 |
| xVCC Propagation Delay and Fall Time With 1-µF Load, 3.3-V Switch, $V_{I(5V)}$ = 5 V | 3 |
| xVCC Propagation Delay and Rise Time With 150-µF Load, 3.3-V Switch, $V_{I(5V)}$ = 5 V | 4 |
| xVCC Propagation Delay and Fall Time With 150-µF Load, 3.3-V Switch, $V_{I(5V)}$ = 5 V | 5 |
| xVCC Propagation Delay and Rise Time With 1-µF Load, 3.3-V Switch, $V_{I(5V)}$ = 0 | 6 |
| xVCC Propagation Delay and Fall Time With 1-µF Load, 3.3-V Switch, $V_{I(5V)}$ = 0 | 7 |
| xVCC Propagation Delay and Rise Time With 150-µF Load, 3.3-V Switch, $V_{I(5V)}$ = 0 | 8 |
| xVCC Propagation Delay and Fall Time With 150-µF Load, 3.3-V Switch, $V_{I(5V)}$ = 0 | 9 |
| xVCC Propagation Delay and Rise Time With 1-µF Load, 5-V Switch | 10 |
| xVCC Propagation Delay and Fall Time With 1-µF Load, 5-V Switch | 11 |
| xVCC Propagation Delay and Rise Time With 150-µF Load, 5-V Switch | 12 |
| xVCC Propagation Delay and Fall Time With 150-µF Load, 5-V Switch | 13 |
| xVPP Propagation Delay and Rise Time With 1-µF Load, 12-V Switch | 14 |
| xVPP Propagation Delay and Fall Time With 1-µF Load, 12-V Switch | 15 |
| xVPP Propagation Delay and Rise Time With 150-µF Load, 12-V Switch | 16 |
| xVPP Propagation Delay and Fall Time With 150-µF Load, 12-V Switch | 17 |

## PARAMETER MEASUREMENT INFORMATION

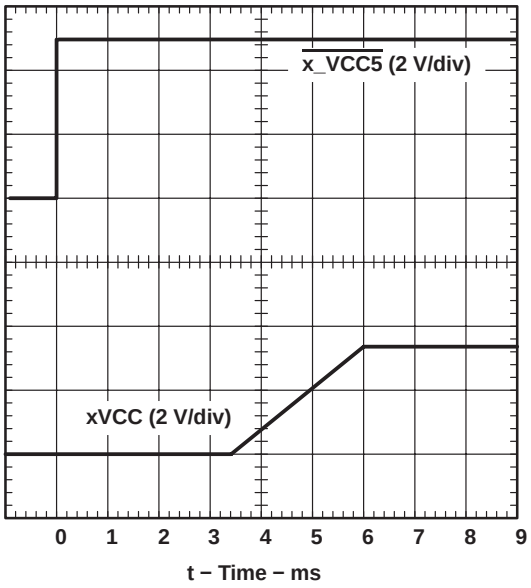



**Figure 2. xVCC Propagation Delay and Rise Time With 1-μF Load, 3.3-V Switch, ($V_{I(5V)}$ = 5 V)**

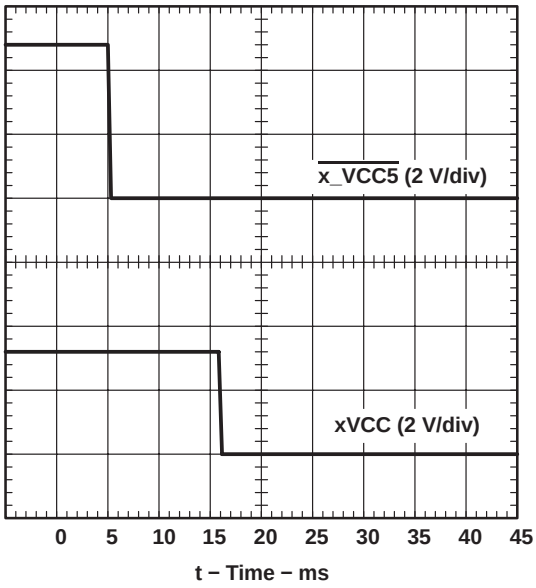



**Figure 3. xVCC Propagation Delay and Fall Time With 1-μF Load, 3.3-V Switch, ($V_{I(5V)}$ = 5 V)**

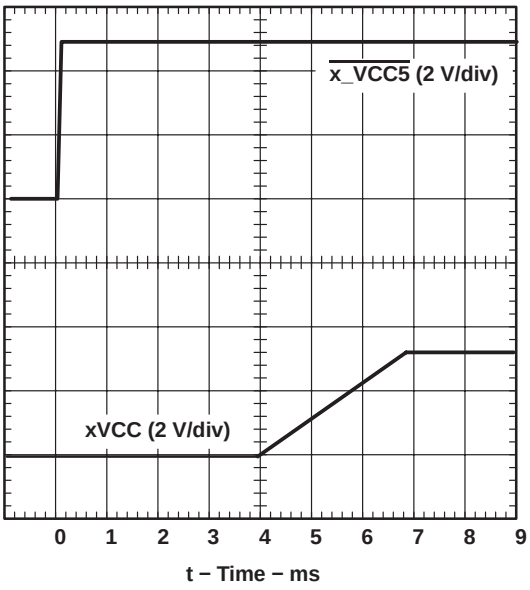



**Figure 4. xVCC Propagation Delay and Rise Time With 150-μF Load, 3.3-V Switch, $V_{I(5V)}$ = 5 V**

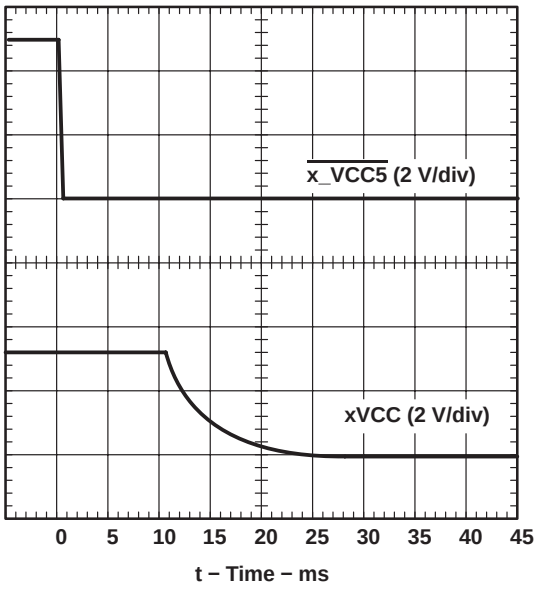



**Figure 5. xVCC Propagation Delay and Fall Time With 150-μF Load, 3.3-V Switch, $V_{I(5V)}$ = 5 V**

## PARAMETER MEASUREMENT INFORMATION

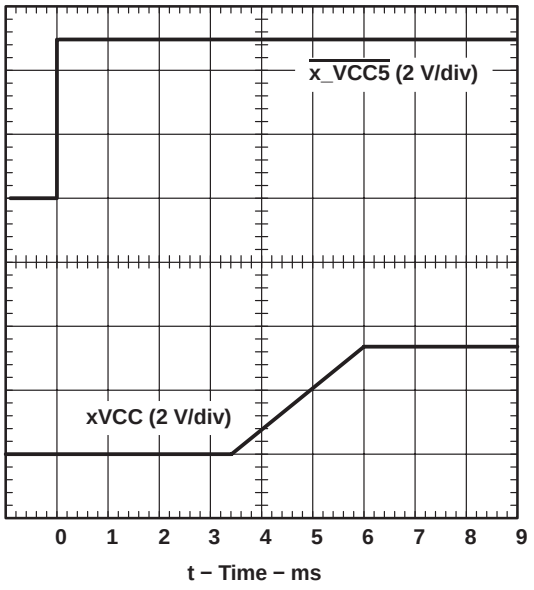



**Figure 6. xVCC Propagation Delay and Rise Time With 1-μF Load, 3.3-V Switch, $V_{I(5V)}$ = 0**

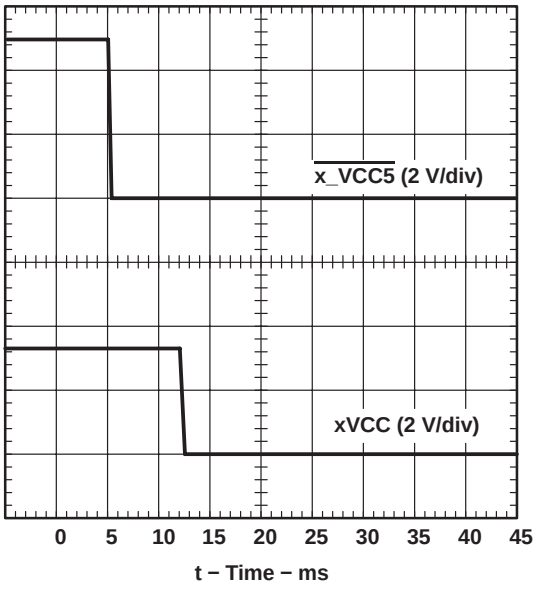



**Figure 7. xVCC Propagation Delay and Fall Time With 1-μF Load, 3.3-V Switch, $V_{I(5V)}$ = 0**

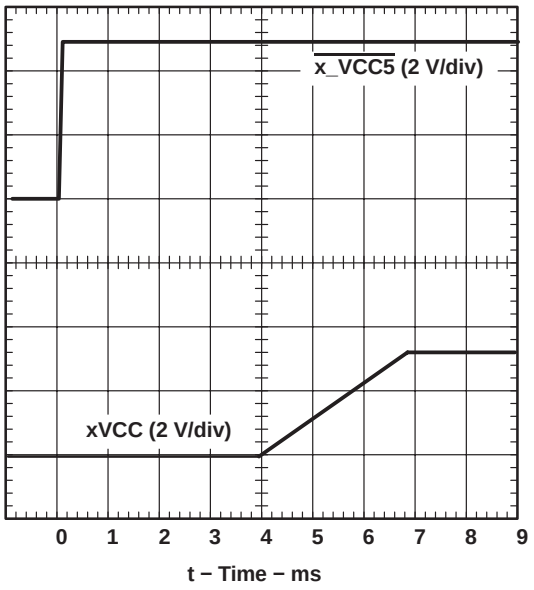



**Figure 8. xVCC Propagation Delay and Rise Time With 150-μF Load, 3.3-V Switch, $V_{I(5V)}$ = 0**

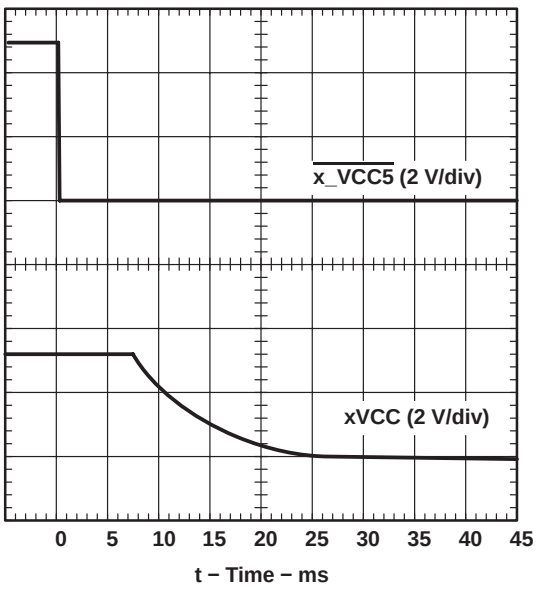



**Figure 9. xVCC Propagation Delay and Fall Time With 150-μF Load, 3.3-V Switch, $V_{I(5V)}$ = 0**

## PARAMETER MEASUREMENT INFORMATION

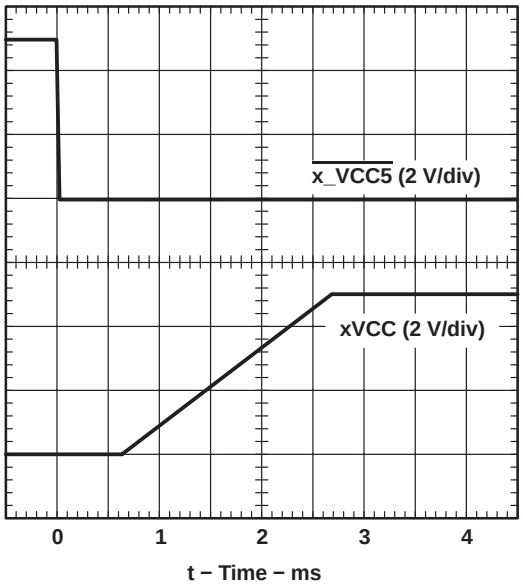



**Figure 10. xVCC Propagation Delay and Rise Time With 1-μF Load, 5-V Switch**

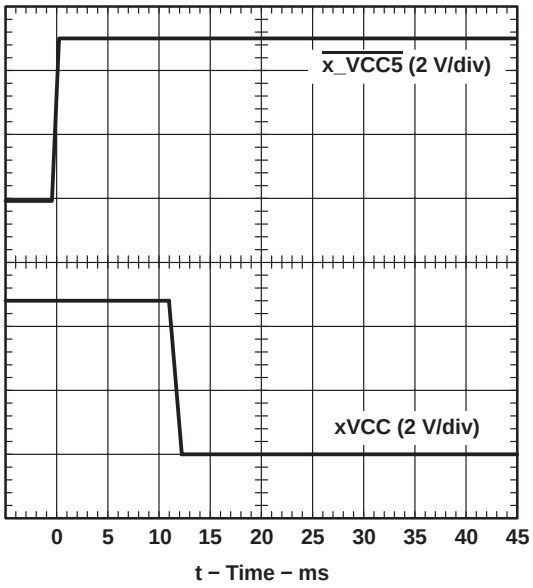



**Figure 11. xVCC Propagation Delay and Fall Time With 1-μF Load, 5-V Switch**

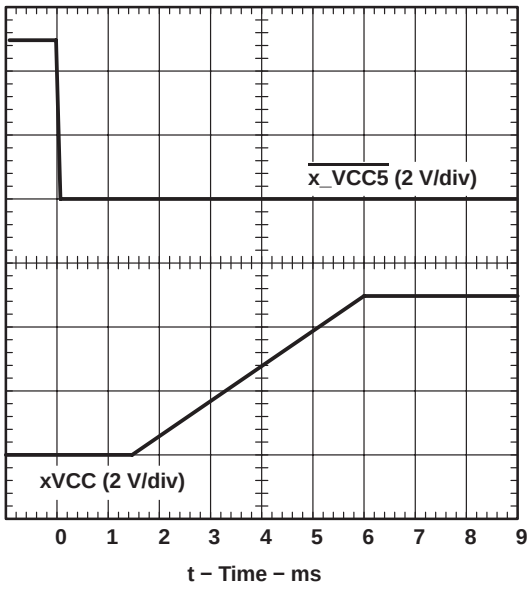



**Figure 12. xVCC Propagation Delay and Rise Time With 150-μF Load, 5-V Switch**

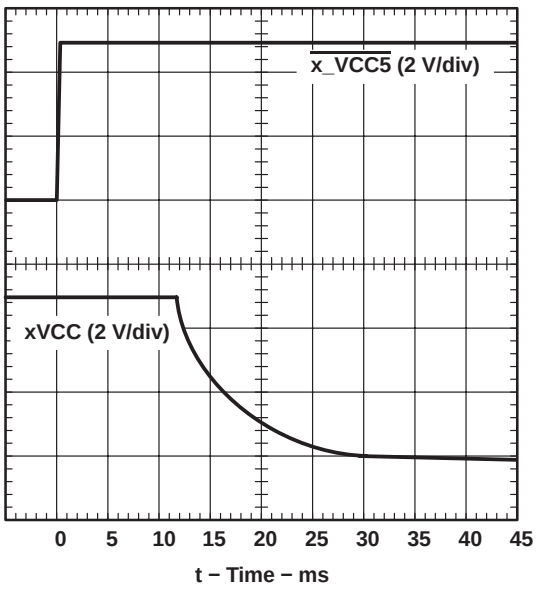



**Figure 13. xVCC Propagation Delay and Fall Time With 150-μF Load, 5-V Switch**

## PARAMETER MEASUREMENT INFORMATION

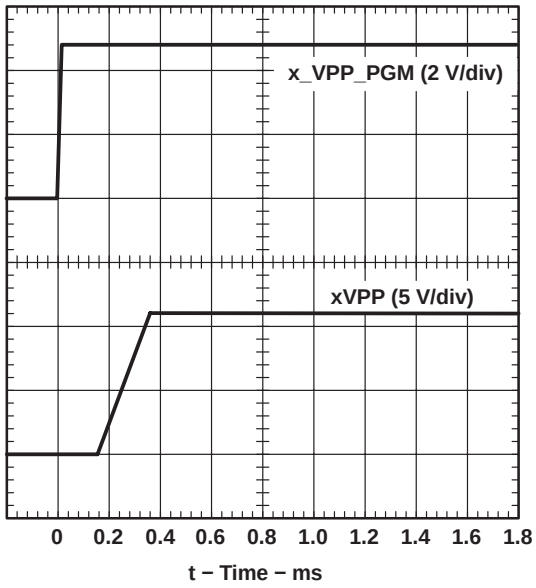



**Figure 14. xVPP Propagation Delay and Rise Time With 1-μF Load, 12-V Switch**

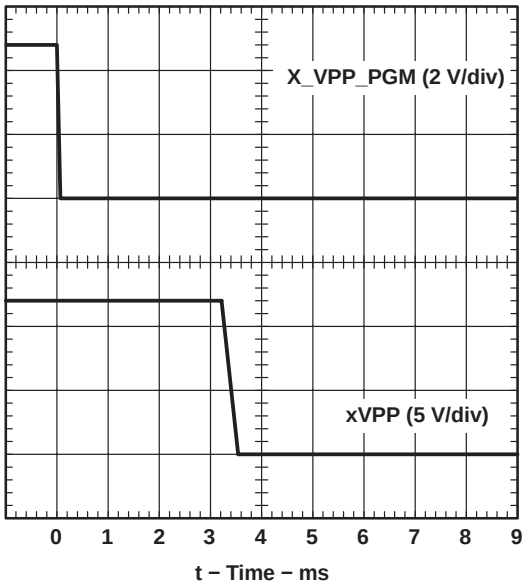



**Figure 15. xVPP Propagation Delay and Fall Time With 1-μF Load, 12-V Switch**

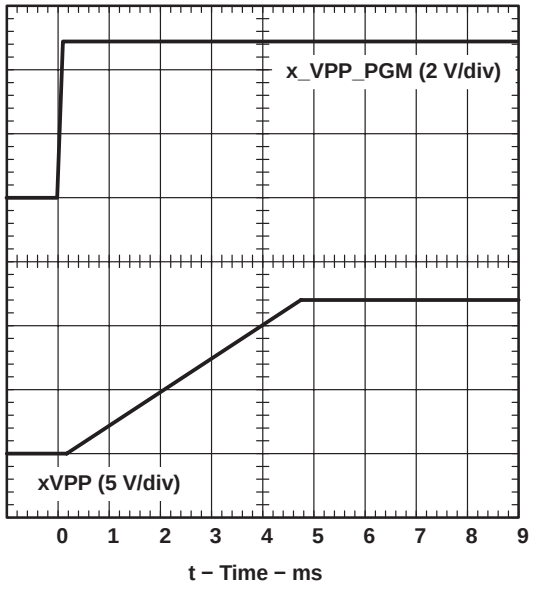



**Figure 16. xVPP Propagation Delay and Rise Time With 150-μF Load, 12-V Switch**

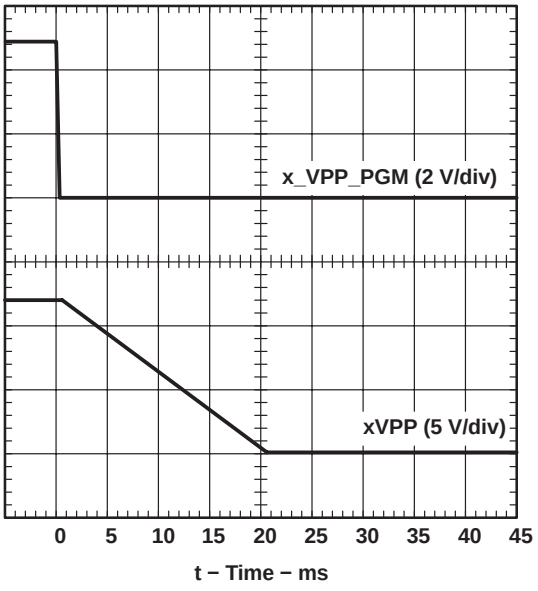



**Figure 17. xVPP Propagation Delay and Fall Time With 150-μF Load, 12-V Switch**

## TYPICAL CHARACTERISTICS

### Table of Graphs

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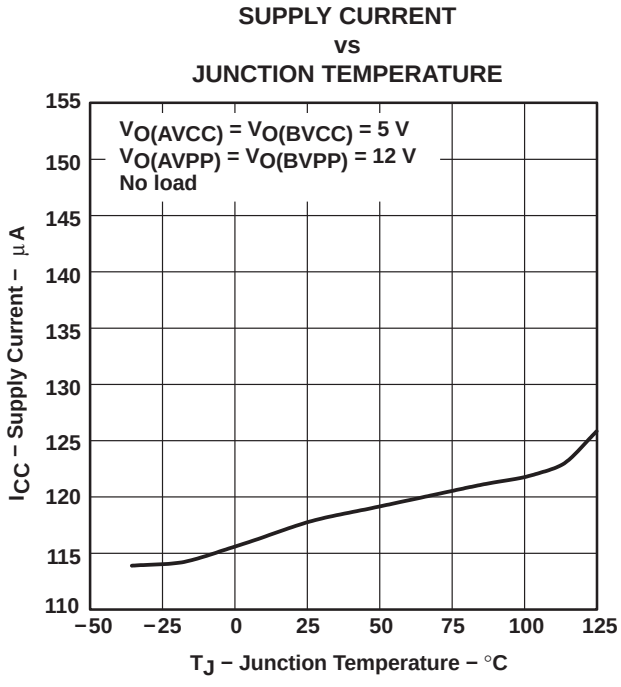



**Figure 18**

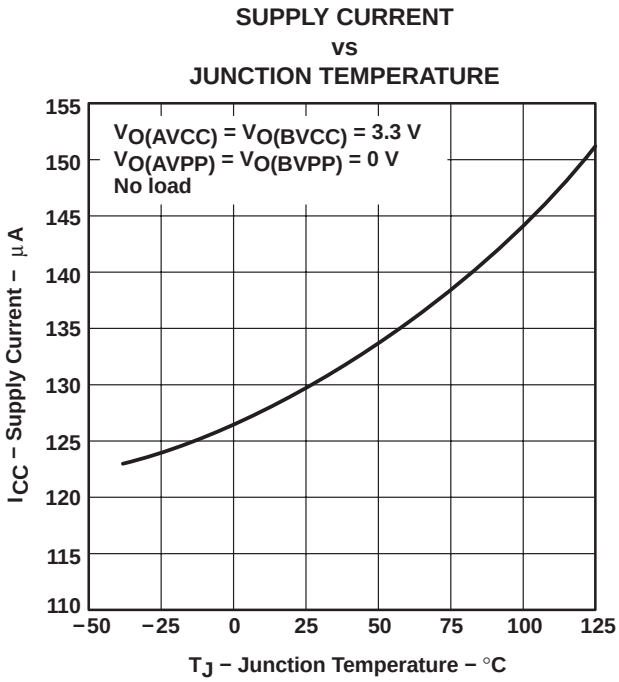



**Figure 19**

## TYPICAL CHARACTERISTICS

3.3-V SWITCH
STATIC DRAIN-SOURCE ON-STATE RESISTANCE
vs
JUNCTION TEMPERATURE

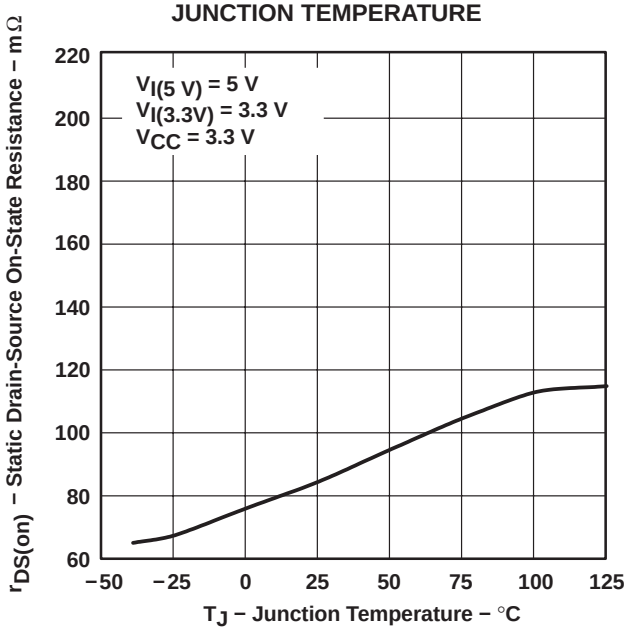



Figure 20

3.3-V SWITCH
STATIC DRAIN-SOURCE ON-STATE RESISTANCE
vs
JUNCTION TEMPERATURE

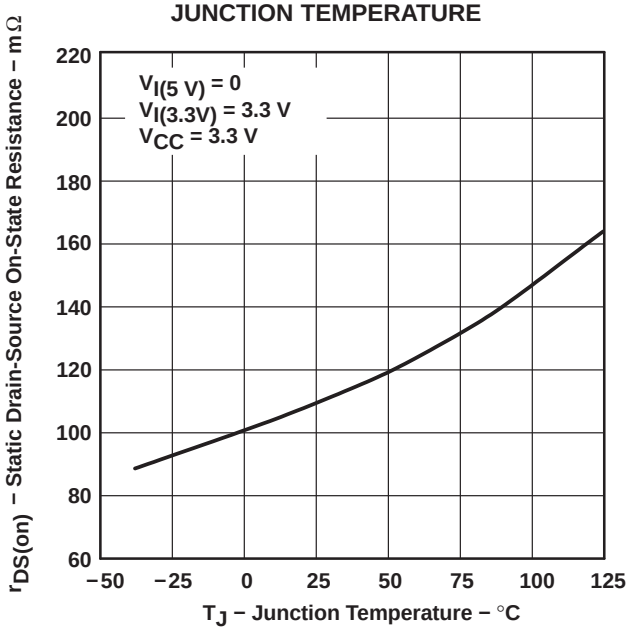



Figure 21

5-V SWITCH
STATIC DRAIN-SOURCE ON-STATE RESISTANCE
vs
JUNCTION TEMPERATURE

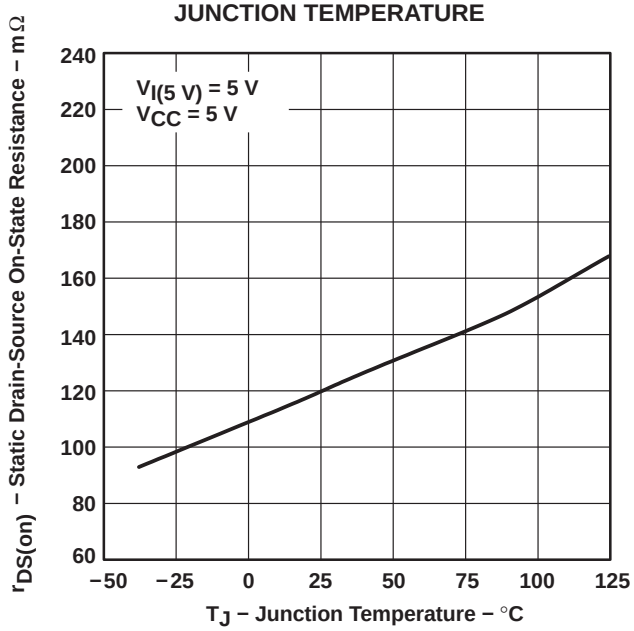



Figure 22

12-V SWITCH
STATIC DRAIN-SOURCE ON-STATE RESISTANCE
vs
JUNCTION TEMPERATURE

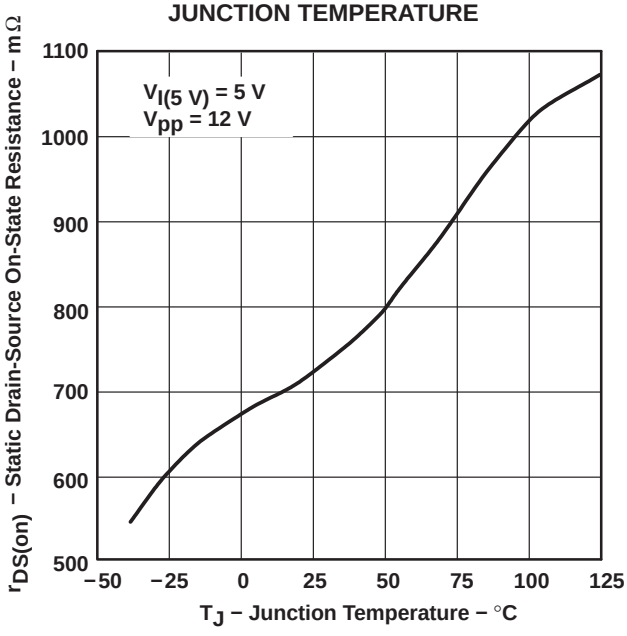



Figure 23

## TYPICAL CHARACTERISTICS

5-V SWITCH
OUTPUT VOLTAGE
vs
OUTPUT CURRENT

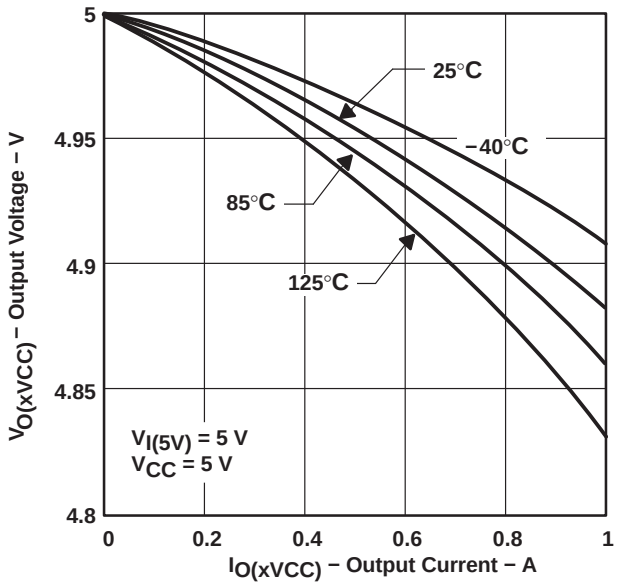



Figure 24

3.3-V SWITCH
OUTPUT VOLTAGE
vs
OUTPUT CURRENT

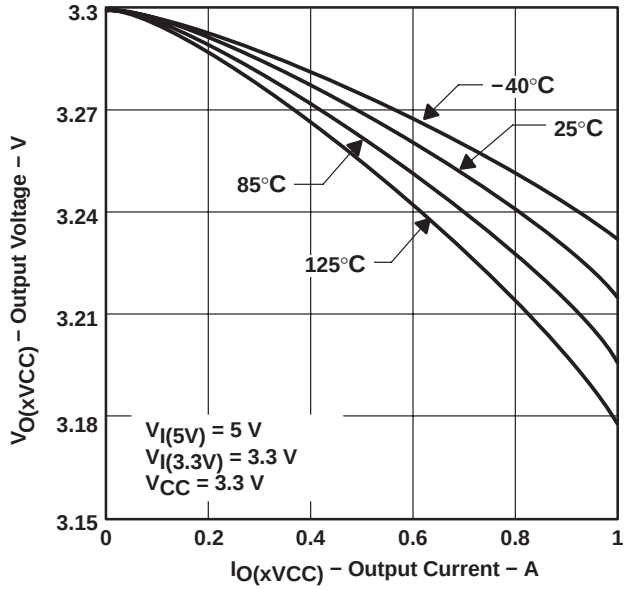



Figure 25

3.3-V SWITCH
OUTPUT VOLTAGE
vs
OUTPUT CURRENT

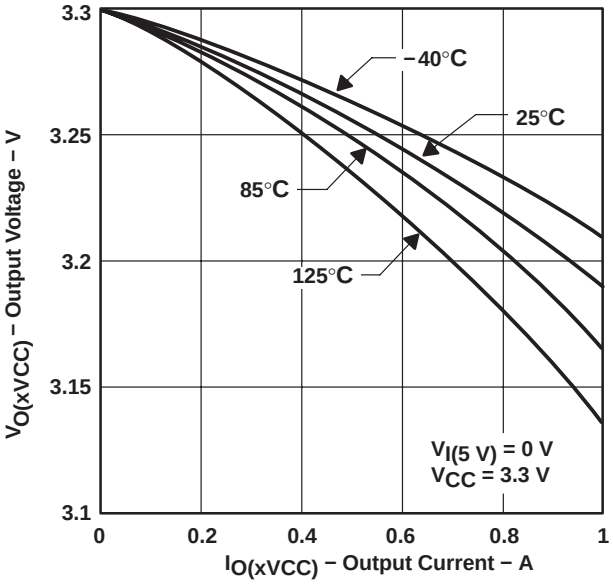



Figure 26

12-V SWITCH
OUTPUT VOLTAGE
vs
OUTPUT CURRENT

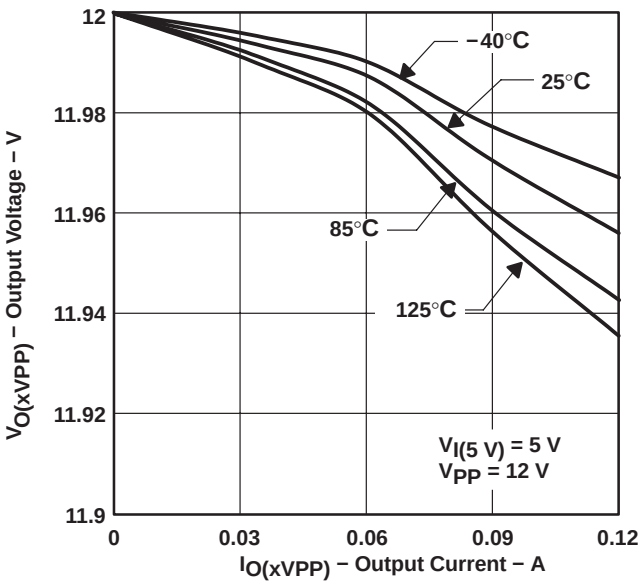



Figure 27

## TYPICAL CHARACTERISTICS

5-V SWITCH
SHORT-CIRCUIT CURRENT
vs
JUNCTION TEMPERATURE

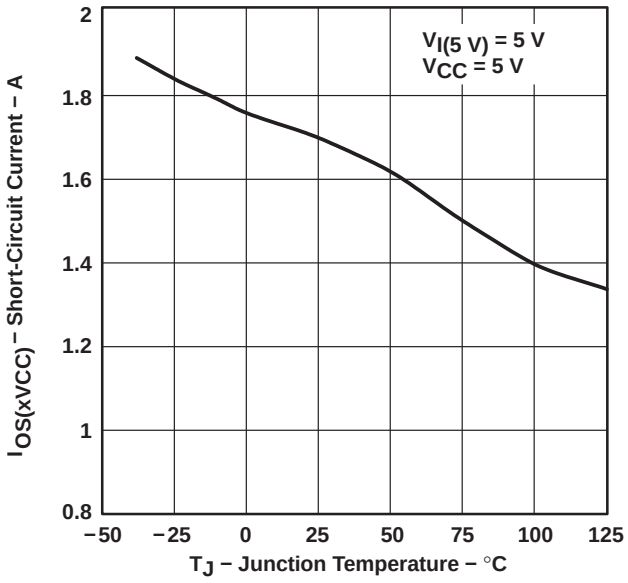



Figure 28

3.3-V SWITCH
SHORT-CIRCUIT CURRENT
vs
JUNCTION TEMPERATURE

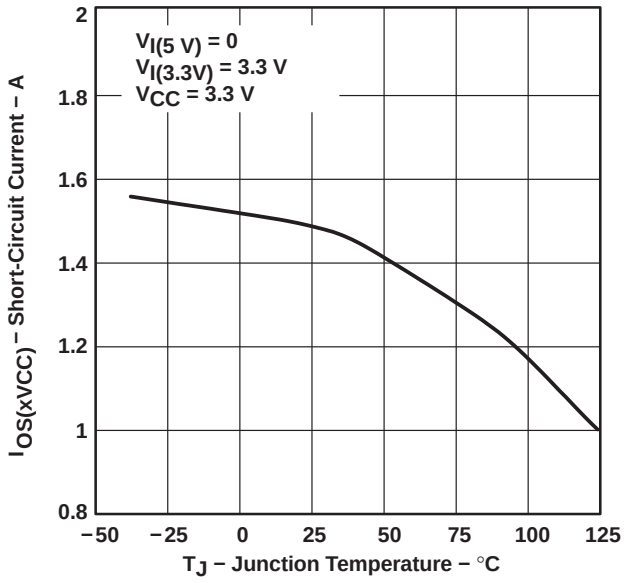



Figure 29

12-V SWITCH
SHORT-CIRCUIT CURRENT
vs
JUNCTION TEMPERATURE

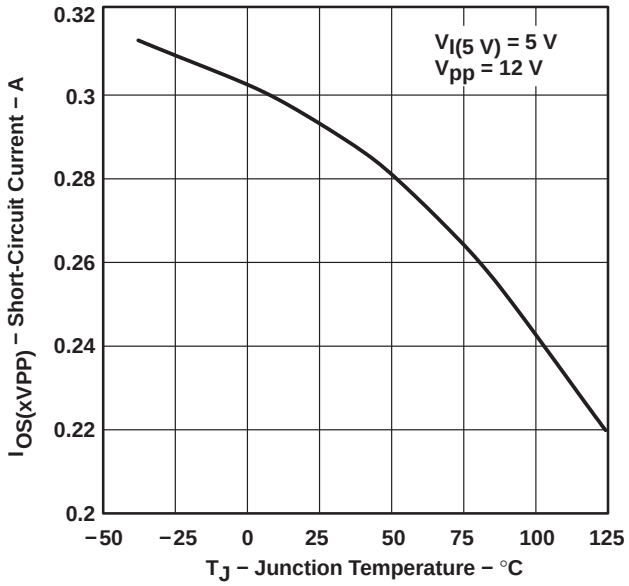



Figure 30

## APPLICATION INFORMATION

### overview

PC Cards were initially introduced as a means to add EEPROM (flash memory) to portable computers with limited on-board memory. The idea of add-in cards quickly took hold; modems, wireless LANs, global positioning satellite system (GPS), multimedia, and hard-disk versions were soon available. As the number of PC Card applications grew, the engineering community quickly recognized the need for a standard to ensure compatibility across platforms. To this end, the PCMCIA was established, comprised of members from leading computer, software, PC Card, and semiconductor manufacturers. One key goal was to realize the *plug-and-play* concept. Cards and hosts from different vendors should be compatible—able to communicate with one another transparently.

#### PC Card power specification

System compatibility also means power compatibility. The most current set of specifications (PC Card Standard) set forth by the PCMCIA committee states that power is to be transferred between the host and the card through eight of 68 terminals of the PC Card connector. This power interface consists of two $V_{CC}$, two $V_{pp}$, and four ground terminals. Multiple $V_{CC}$ and ground terminals minimize connector-terminal and line resistance. The two $V_{pp}$ terminals were originally specified as separate signals, but are commonly tied together in the host to form a single node to minimize voltage losses. Card primary power is supplied through the $V_{CC}$ terminals; flash-memory programming and erase voltage is supplied through the $V_{pp}$ terminals.

#### designing for voltage regulation

The current PCMCIA specification for output-voltage regulation ($V_{O(reg)}$) of the 5-V output is 5% (250 mV). In a typical PC power-system design, the power supply has an output-voltage regulation ($V_{PS(reg)}$) of 2% (100 mV). Also, a voltage drop from the power supply to the PC Card will result from resistive losses ($V_{PCB}$) in the PCB traces and the PCMCIA connector. A typical design would limit the total of these resistive losses to less than 1% (50 mV) of the output voltage. Therefore, the allowable voltage drop ($V_{DS}$) for the TPS2205 would be the PCMCIA voltage regulation less the power supply regulation and less the PCB and connector resistive drops:

$$V_{DS} = V_{O(reg)} - V_{PS(reg)} - V_{PCB}$$

Typically, this would leave 100 mV for the allowable voltage drop across the TPS2205. The voltage drop is the output current multiplied by the switch resistance of the TPS2205. Therefore, the maximum output current that can be delivered to the PC Card in regulation is the allowable voltage drop across the TPS2205 divided by the output switch resistance.

$$I_O max = \frac{V_{DS}}{r_{DS(on)}}$$

The xVCC outputs have been designed to deliver 700 mA at 5 V within regulation over the operating temperature range. Current proposals for the PCMCIA specifications are to limit the power dissipated in the PCMCIA slot to 3 W. With an input voltage of 5 V, 700 mA continous is the maximum current that can be delivered to the PC Card. The TPS2205 is capable of delivering up to 1 A continuously, but during worst-case conditions the output may not be within regulation. This is generally acceptable because the majority of PC Cards require less than 700 mA continuous. Some cards require higher peak currents (disk drives during initial platter spin-up), but it is generally acceptable for small voltage sags to occur during these peak currents.

The xVCC outputs have been designed to deliver 1 A continuously at 3.3 V within regulation over the operating temperature range. The PCMCIA specification for output voltage regulation of the 3.3-V output is 300 mV. Using the voltage drop percentages (2%) for power supply regulation and PCB resistive loss (1%), the allowable voltage drop for the 3.3 V switch is 200 mV.

The xVPP outputs have been designed to deliver 150 mA continuously at 12 V.

## APPLICATION INFORMATION

### overcurrent and overtemperature protection

PC Cards are inherently subject to damage that can result from mishandling. Host systems require protection against short-circuited cards that could lead to power supply or PCB-trace damage. Even systems sufficiently robust to withstand a short circuit would still undergo rapid battery discharge into the damaged PC Card, resulting in the rather sudden and unacceptable loss of system power. Most hosts include fuses for protection. The reliability of fused systems is poor, as blown fuses require troubleshooting and repair, usually by the manufacturer.

The TPS2205 takes a two-pronged approach to overcurrent protection. First, instead of fuses, sense FETs monitor each of the power outputs. Excessive current generates an error signal that linearly limits the output current, preventing host damage or failure. Sense FETs, unlike sense resistors or polyfuses, have an advantage in that they do not add to the series resistance of the switch and thus produce no additional voltage losses. Second, when an overcurrent condition is detected, the TPS2205 asserts a signal at $\overline{OC}$ that can be monitored by the microprocessor to initiate diagnostics and/or send the user a warning message. In the event that an overcurrent condition persists, causing the IC to exceed its maximum junction temperature, thermal-protection circuitry activates, shutting down all power outputs until the device cools to within a safe operating region.

### 12-V supply not required

Most PC Card switches use the externally supplied 12-V $V_{pp}$ power for switch-gate drive and other chip functions, which requires that power be present at all times. The TPS2205 offers considerable power savings by using an internal charge pump to generate the required higher voltages from the 5-V or 3.3-V input; therefore, the external 12-V supply can be disabled except when needed for flash-memory functions, thereby extending battery lifetime. Do not ground the 12-V inputs when the 12-V input is not used. Additional power savings are realized by the TPS2205 during a software shutdown in which quiescent current drops to a maximum of 1 μA.

### backward compatibility and 3.3-V low-voltage mode

The TPS2205 is backward compatible with the TPS2201, with the following considerations. Pin 25 ($V_{DD}$ on TPS2201) is a no connect because bias current is derived from either the 3.3-V input pin or the 5-V input pin. Also, the TPS2205 does not have the APWR_GOOD or BPWR_GOOD VPP reporting outputs. These are left as no connects.

The TPS2205 operates in 3.3-V low-voltage mode when 3.3 V is the only available input voltage ($V_{I(5V)}$=0). This allows host and PC Cards to be operated in low-power 3.3-V-only modes such as sleep modes or pager modes. Note that in this operation mode, the TPS2205 derives its bias current from the 3.3-V input pin and only 3.3 V can be delivered to the PC Card. The 3.3-V switch resistance will be increased, but the added switch resistance should not be critical, because only a small amount of current is delivered in this mode. If 6% (198 mV) is allowed for the 3.3-V switch voltage drop, a 500-mΩ switch could deliver over 350 mA to the PC Card.

### voltage-transitioning requirement

PC Cards, like portables, are migrating from 5 V to 3.3 V to minimize power consumption, optimize board space, and increase logic speeds. The TPS2205 is designed to meet all combinations of power delivery as currently defined in the PCMCIA standard. The latest protocol accommodates mixed 3.3-V/5-V systems by first powering the card with 5 V, then polling it to determine its 3.3-V compatibility. The PCMCIA specification requires that the capacitors on 3.3-V-compatible cards be discharged to below 0.8 V before applying 3.3-V power. This ensures that sensitive 3.3-V circuitry is not subjected to any residual 5-V charge and functions as a power reset. The TPS2205 offers a selectable $V_{CC}$ and $V_{pp}$ ground state, in accordance with PCMCIA 3.3-V/5-V switching specifications, to fully discharge the card capacitors while switching between $V_{CC}$ voltages.

## APPLICATION INFORMATION

### output ground switches

Several PCMCIA power-distribution switches on the market do not have an active-grounding FET switch. These devices do not meet the PC Card specification requiring a discharge of $V_{CC}$ within 100 ms. PC Card resistance can not be relied on to provide a discharge path for voltages stored on PC Card capacitance because of possible high-impedance isolation by power-management schemes. A method commonly shown to alleviate this problem is to add to the switch output an external 100-kΩ resistor in parallel with the PC Card. Considering that this is the only discharge path to ground, a timing analysis shows that the RC time constant delays the required discharge time to more than 2 seconds. The only way to ensure timing compatibility with PC Card standards is to use a power-distribution switch that has an internal ground switch, like that of the TPS22xx family, or add an external ground FET to each of the output lines with the control logic necessary to select it.

In summary, the TPS2205 is a complete single-chip dual-slot PC Card power interface. It meets all currently defined PCMCIA specifications for power delivery in 5-V, 3.3-V, and mixed systems, and offers a serial control interface. The TPS2205 offers functionality, power savings, overcurrent and thermal protection, and fault reporting in one 30-pin SSOP surface-mount package, for maximum value added to new portable designs.

### power-supply considerations

The TPS2205 has multiple pins for each of its 3.3-V, 5-V, and 12-V power inputs and for the switched $V_{CC}$ outputs. Any individual pin can conduct the rated input or output current. Unless all pins are connected in parallel, the series resistance is significantly higher than that specified, resulting in increased voltage drops and lost power. Both 12-V inputs must be connected for proper $V_{pp}$ switching; it is recommended that all input and output power pins be paralleled for optimum operation.

Although the TPS2205 is fairly immune to power input fluctuations and noise, it is generally considered good design practice to bypass power supplies, typically with a 1-µF electrolytic or tantalum capacitor paralleled by a 0.047-µF to 0.1-µF ceramic capacitor. It is strongly recommended that the switched $V_{CC}$ and $V_{pp}$ outputs be bypassed with a 0.1-µF or larger capacitor; doing so improves the immunity of the TPS2205 to electrostatic discharge (ESD). Care should be taken to minimize the inductance of PCB traces between the TPS2205 and the load. High switching currents can produce large negative-voltage transients, which forward biases substrate diodes, resulting in unpredictable performance. Similary, no pin should be taken below −0.3 V.

### overcurrent and thermal protection

The TPS2205 uses sense FETs to check for overcurrent conditions in each of the $V_{CC}$ and $V_{pp}$ outputs. Unlike sense resistors or polyfuses, these FETs do not add to the series resistance of the switch; therefore, voltage and power losses are reduced. Overcurrent sensing is applied to each output separately. When an overcurrent condition is detected, only the power output affected is limited; all other power outputs continue to function normally. The $\overline{OC}$ indicator, normally a logic high, is a logic low when any overcurrent condition is detected, providing for initiation of system diagnostics and/or sending a warning message to the user.

During power up, the TPS2205 controls the rise time of the $V_{CC}$ and $V_{pp}$ outputs and limits the current into a faulty card or connector. If a short circuit is applied after power is established (e.g., hot insertion of a bad card), current is initially limited only by the impedance between the short and the power supply. In extreme cases, as much as 10 A to 15 A may flow into the short before the current limiting of the TPS2205 engages. If the $V_{CC}$ or $V_{pp}$ outputs are driven below ground, the TPS2205 may latch nondestructively in an off state. Cycling power will reestablish normal operation.

Overcurrent limiting for the $V_{CC}$ outputs is designed to activate if powered up into a short in the range of 1 A to 2.2 A, typically at about 1.6 A. The $V_{pp}$ outputs limit from 120 mA to 400 mA, typically around 280 mA. The protection circuitry acts by linearly limiting the current passing through the switch rather than initiating a full shutdown of the supply. Shutdown occurs only during thermal limiting.

## APPLICATION INFORMATION

### overcurrent and thermal protection (continued)

Thermal limiting prevents destruction of the IC from overheating if the package power-dissipation ratings are exceeded. Thermal limiting disables all power outputs (both A and B slots) until the device has cooled.

### calculating junction temperature

The switch resistance, $r_{DS(on)}$, is dependent on the junction temperature, $T_J$, of the die. The junction temperature is dependent on both $r_{DS(on)}$ and the current through the switch. To calculate $T_J$, first find $r_{DS(on)}$ from Figures 20, 21, 22, and 23 using an initial temperature estimate about 50°C above ambient. Then calculate the power dissipation for each switch, using the formula:

$$P_D = r_{DS(on)} \times I^2$$

Next, sum the power dissipation and calculate the junction temperature:

$$T_J = \left(\Sigma P_D \times R_{\theta JA}\right) + T_A,\ R_{\theta JA} = 108\ ^\circ C/W$$

Compare the calculated junction temperature with the initial temperature estimate. If the temperatures are not within a few degrees of each other, recalculate using the calculated temperature as the initial estimate.

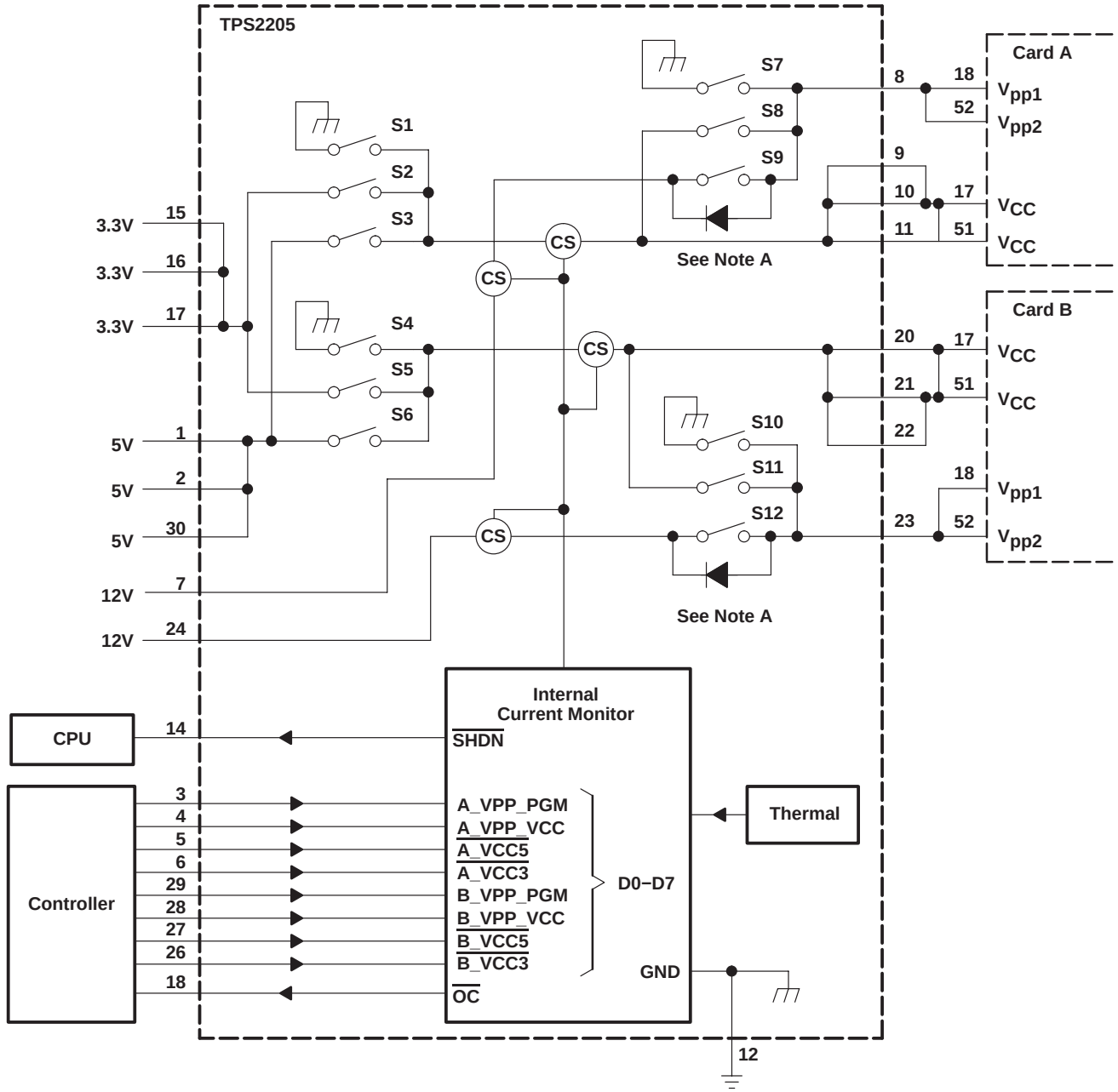
### logic input and outputs

The TPS2205 was designed to be compatible with most popular PCMCIA controllers and current PCMCIA and JEIDA standards. However, some controllers require slightly counterintuitive connections to achieve desired output states. The TPS2205 control logic inputs $\overline{A_VCC3}$, $\overline{A_VCC5}$, $\overline{B_VCC3}$ and $\overline{B_VCC5}$ are defined active low (see Figure 31 and control-logic table). As such, they are directly compatible with the logic outputs of the Cirrus Logic CL-PD6720 controller.

The shutdown input ($\overline{SHDN}$) of the TPS2205, when held at a logic low, places all $V_{CC}$ and $V_{pp}$ outputs in a high-impedance state and reduces chip quiescent current to 1 μA to conserve battery power.

An overcurrent output ($\overline{OC}$) is provided to indicate an overcurrent condition in any of the $V_{CC}$ or $V_{pp}$ supplies (see discussion above).

## APPLICATION INFORMATION




NOTE A: MOSFET switches S9 and S12 have a back-gate diode from the source to the drain. Unused switch inputs ;should never be grounded.

**Figure 31. Internal Switching Matrix**

## APPLICATION INFORMATION

### TPS2205 control logic

**AVPP**

| CONTROL SIGNALS | | | INTERNAL SWITCH SETTINGS | | | OUTPUT |
|---|---|---|---|---|---|---|
| D8 $\overline{\text{SHDN}}$ | D0 A_VPP_PGM | D1 A_VPP_VCC | S7 | S8 | S9 | VAVPP |
| 1 | 0 | 0 | CLOSED | OPEN | OPEN | 0 V |
| 1 | 0 | 1 | OPEN | CLOSED | OPEN | VCC† |
| 1 | 1 | 0 | OPEN | OPEN | CLOSED | VPP(12 V) |
| 1 | 1 | 1 | OPEN | OPEN | OPEN | Hi-Z |
| 0 | X | X | OPEN | OPEN | OPEN | Hi-Z |

**BVPP**

| CONTROL SIGNALS | | | INTERNAL SWITCH SETTINGS | | | OUTPUT |
|---|---|---|---|---|---|---|
| D8 $\overline{\text{SHDN}}$ | D4 B_VPP_PGM | D5 B_VPP_VCC | S10 | S11 | S12 | VBVPP |
| 1 | 0 | 0 | CLOSED | OPEN | OPEN | 0 V |
| 1 | 0 | 1 | OPEN | CLOSED | OPEN | VCC‡ |
| 1 | 1 | 0 | OPEN | OPEN | CLOSED | VPP(12 V) |
| 1 | 1 | 1 | OPEN | OPEN | OPEN | Hi-Z |
| 0 | X | X | OPEN | OPEN | OPEN | Hi-Z |

**AVCC**

| CONTROL SIGNALS | | | INTERNAL SWITCH SETTINGS | | | OUTPUT |
|---|---|---|---|---|---|---|
| D8 $\overline{\text{SHDN}}$ | D3 $\overline{\text{A_VCC3}}$ | D2 $\overline{\text{A_VCC5}}$ | S1 | S2 | S3 | VAVCC |
| 1 | 0 | 0 | CLOSED | OPEN | OPEN | 0 V |
| 1 | 0 | 1 | OPEN | CLOSED | OPEN | 3.3 V |
| 1 | 1 | 0 | OPEN | OPEN | CLOSED | 5 V |
| 1 | 1 | 1 | CLOSED | OPEN | OPEN | 0 V |
| 0 | X | X | OPEN | OPEN | OPEN | Hi-Z |

**BVCC**

| CONTROL SIGNALS | | | INTERNAL SWITCH SETTINGS | | | OUTPUT |
|---|---|---|---|---|---|---|
| D8 $\overline{\text{SHDN}}$ | D6 $\overline{\text{B_VCC3}}$ | D7 $\overline{\text{B_VCC5}}$ | S4 | S5 | S6 | VBVCC |
| 1 | 0 | 0 | CLOSED | OPEN | OPEN | 0 V |
| 1 | 0 | 1 | OPEN | CLOSED | OPEN | 3.3 V |
| 1 | 1 | 0 | OPEN | OPEN | CLOSED | 5 V |
| 1 | 1 | 1 | CLOSED | OPEN | OPEN | 0 V |
| 0 | X | X | OPEN | OPEN | OPEN | Hi-Z |

† Output depends on AVCC
‡ Output depends on BVCC

### ESD protection

All TPS2205 inputs and outputs incorporate ESD-protection circuitry designed to withstand a 2-kV human-body-model discharge as defined in MIL-STD-883C, Method 3015. The $V_{CC}$ and $V_{pp}$ outputs can be exposed to potentially higher discharges from the external environment through the PC Card connector. Bypassing the outputs with 0.1-µF capacitors protects the devices from discharges up to 10 kV.

## APPLICATION INFORMATION

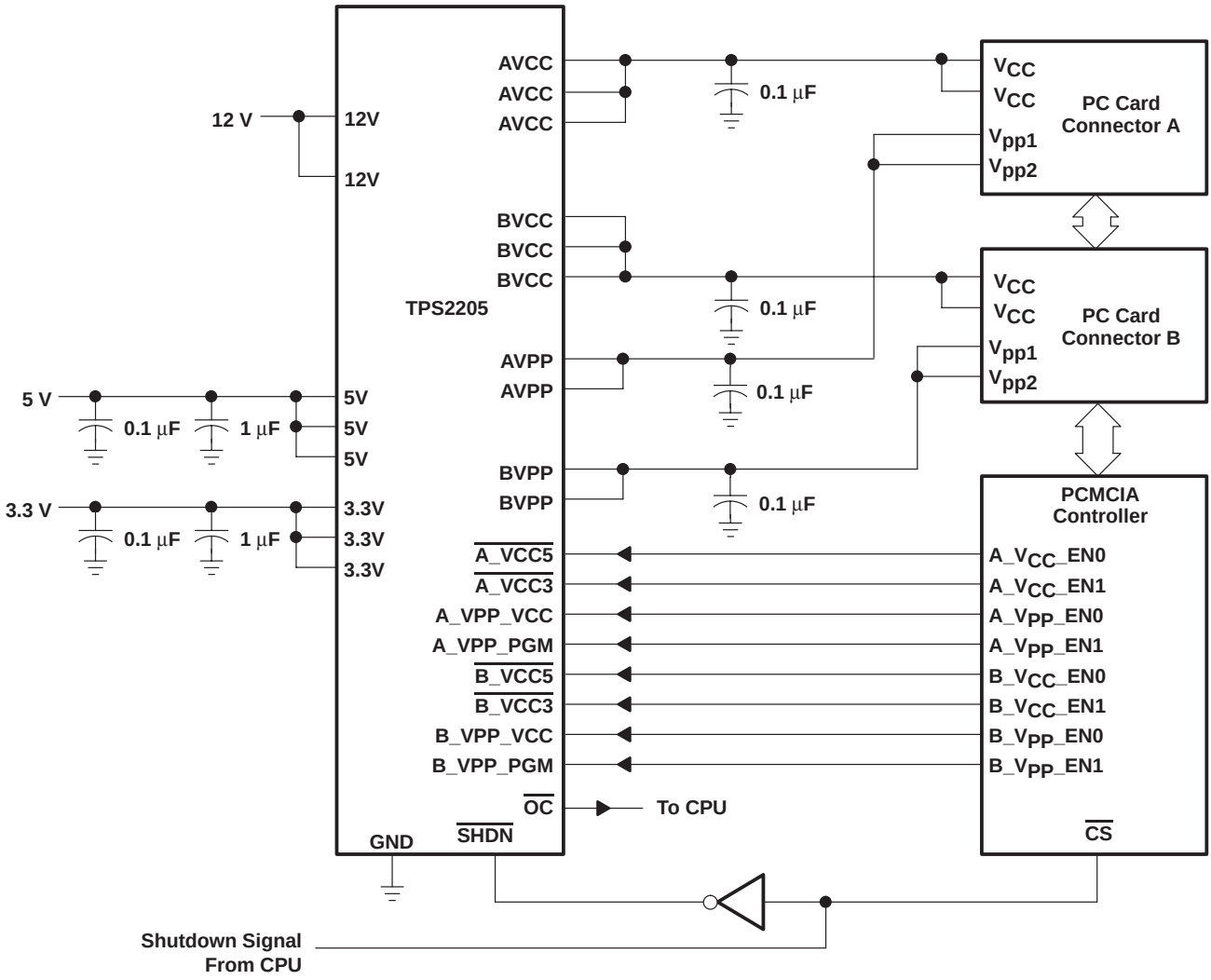


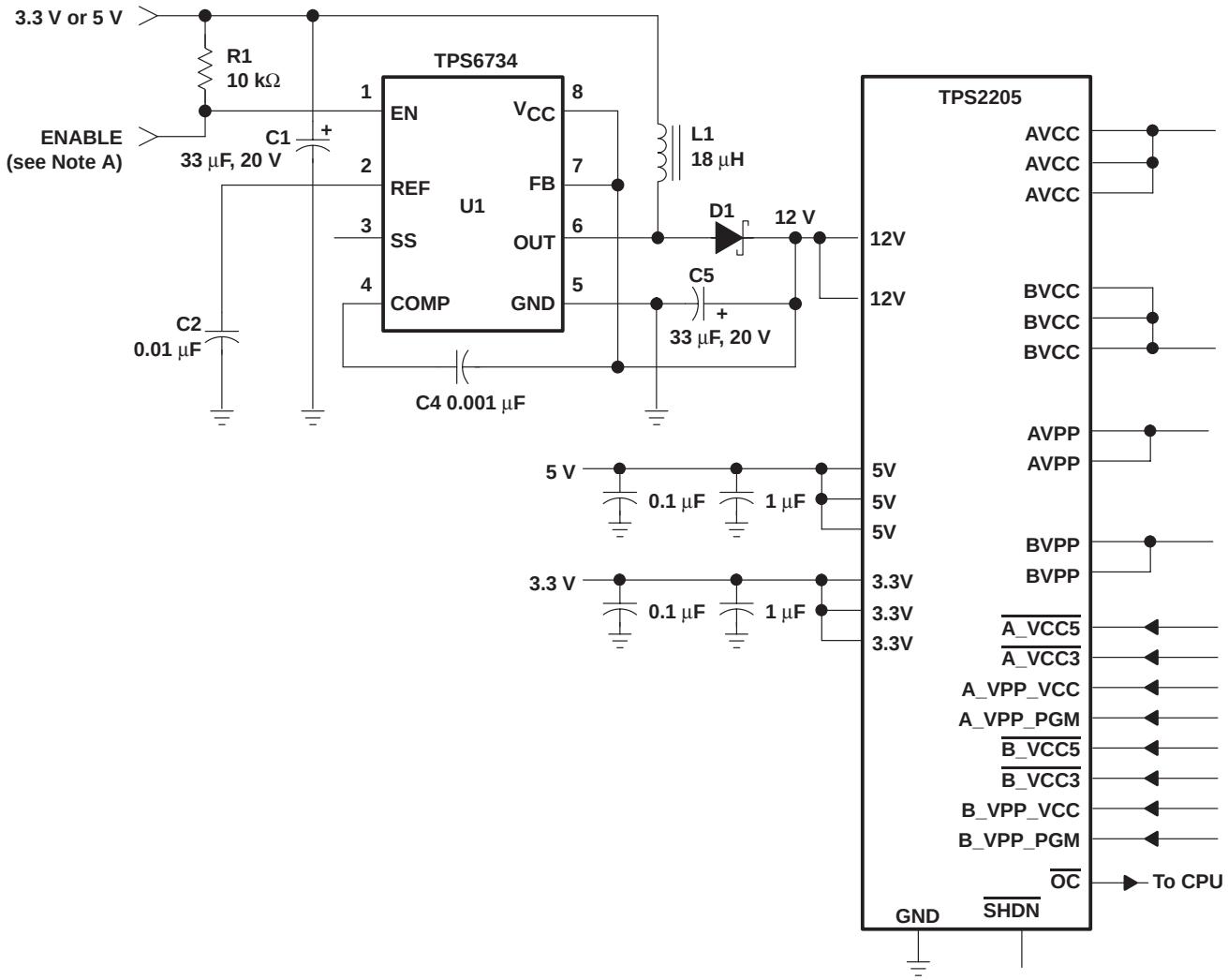

**Figure 32. Detailed Interconnections and Capacitor Recommendations**

## APPLICATION INFORMATION

### 12-V flash memory supply

The TPS6734 is a fixed 12-V output boost converter capable of delivering 120 mA from inputs as low as 2.7 V. The device is pin-for-pin compatible with the MAX734 regulator and offers the following advantages: lower supply current, wider operating input-voltage range, and higher output currents. As shown in Figure 1, the only external components required are: an inductor, a Schottky rectifier, an output filter capacitor, an input filter capacitor, and a small capacitor for loop compensation. The entire converter occupies less than 0.7 $in^2$ of PCB space when implemented with surface-mount components. An enable input is provided to shut the converter down and reduce the supply current to 3 μA when 12 V is not needed.

The TPS6734 is a 170-kHz current-mode PWM ( pulse-width modulation) controller with an n-channel MOSFET power switch. Gate drive for the switch is derived from the 12-V output after start-up to minimize the die area needed to realize the 0.7-Ω MOSFET and improve efficiency at input voltages below 5 V. Soft start is accomplished with the addition of one small capacitor. A 1.22-V reference (pin 2) is brought out for external use. For additional information, see the TPS6734 data sheet (SLVS127).




NOTE A: The enable terminal can be tied to a generall purpose I/O terminal on the PCMCIA controller or tied high.

**Figure 33. TPS2205 with TPS6734 12-V, 120-mA Supply**

## PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) |
|---|---|---|---|---|---|---|---|---|
| TPS2205IDAP | ACTIVE | HTSSOP | DAP | 32 | 46 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| TPS2205IDAPG4 | ACTIVE | HTSSOP | DAP | 32 | 46 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| TPS2205IDAPR | ACTIVE | HTSSOP | DAP | 32 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| TPS2205IDAPRG4 | ACTIVE | HTSSOP | DAP | 32 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| TPS2205IDB | ACTIVE | SSOP | DB | 30 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS2205IDBG4 | ACTIVE | SSOP | DB | 30 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS2205IDBLE | OBSOLETE | SSOP | DB | 30 | | TBD | Call TI | Call TI |
| TPS2205IDBR | ACTIVE | SSOP | DB | 30 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS2205IDBRG4 | ACTIVE | SSOP | DB | 30 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS2205IDF | ACTIVE | SSOP | DF | 30 | 25 | Pb-Free (RoHS) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS2205IDFLE | OBSOLETE | SSOP | DF | 30 | | TBD | Call TI | Call TI |
| TPS2205IDFR | ACTIVE | SSOP | DF | 30 | 1000 | Pb-Free (RoHS) | CU NIPDAU | Level-1-260C-UNLIM |

(1) The marketing status values are defined as follows:
**ACTIVE:** Product device recommended for new designs.
**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.
**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
**TBD:** The Pb-Free/Green conversion plan has not been defined.
**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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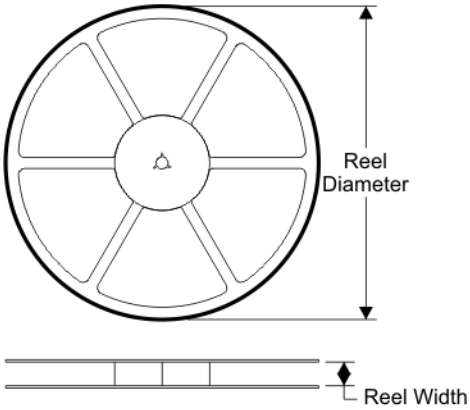
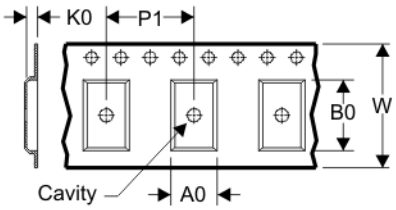
## TAPE AND REEL BOX INFORMATION

**REEL DIMENSIONS**

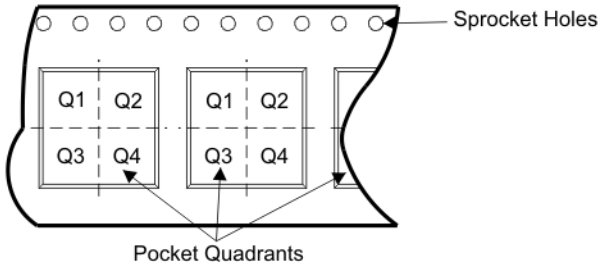



**TAPE DIMENSIONS**



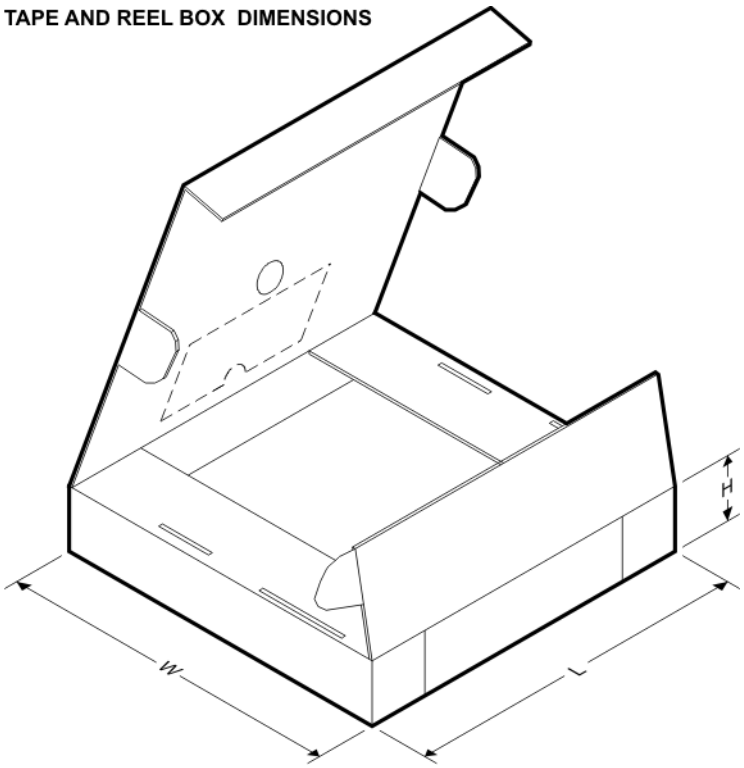

| | |
|---|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**




| Device | Package | Pins | Site | Reel Diameter (mm) | Reel Width (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---|---|---|---|---|---|---|---|---|---|---|---|
| TPS2205IDAPR | DAP | 32 | SITE 60 | 330 | 24 | 8.6 | 11.5 | 1.6 | 12 | 24 | Q1 |
| TPS2205IDBR | DB | 30 | SITE 41 | 330 | 16 | 8.2 | 10.5 | 2.5 | 12 | 16 | Q1 |
| TPS2205IDFR | DF | 30 | SITE 32 | 330 | 24 | 10.8 | 13.2 | 3.25 | 16 | 24 | Q1 |

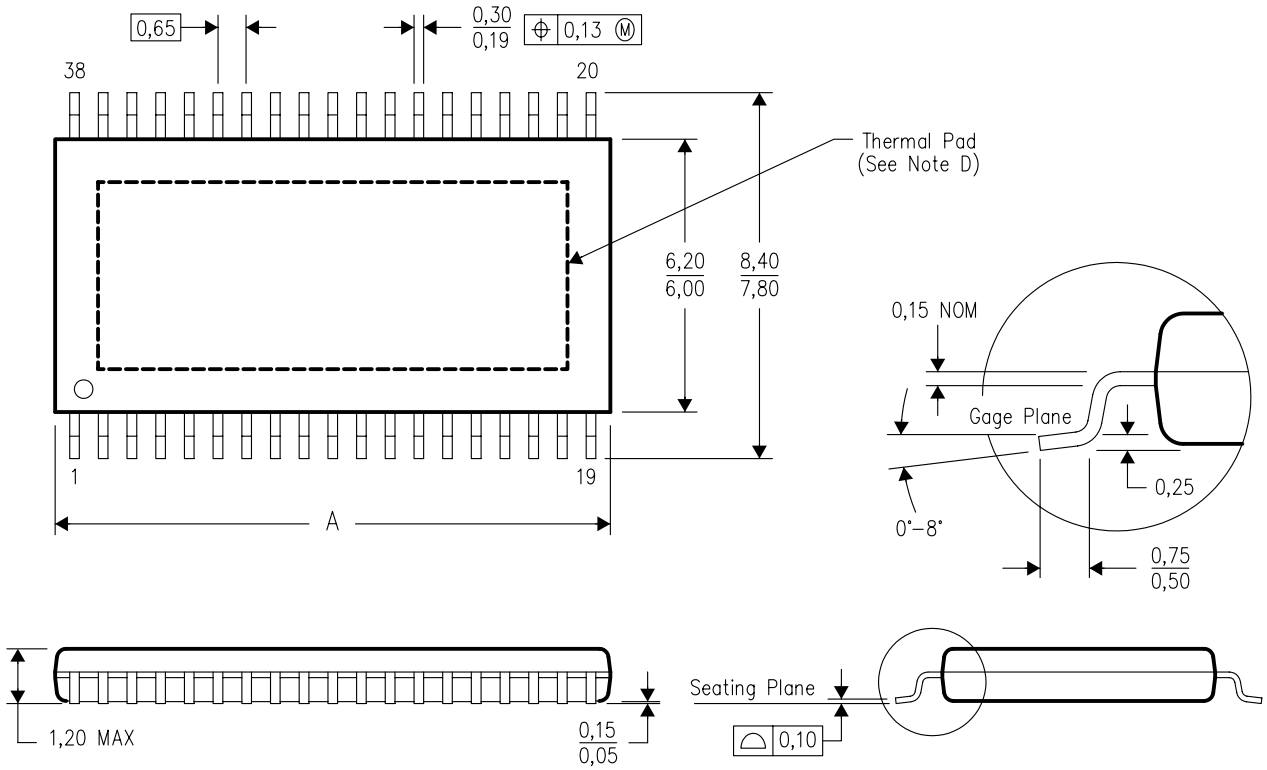
**TAPE AND REEL BOX DIMENSIONS**




| Device | Package | Pins | Site | Length (mm) | Width (mm) | Height (mm) |
|---|---|---|---|---|---|---|
| TPS2205IDAPR | DAP | 32 | SITE 60 | 367.0 | 367.0 | 45.0 |
| TPS2205IDBR | DB | 30 | SITE 41 | 346.0 | 346.0 | 33.0 |
| TPS2205IDFR | DF | 30 | SITE 32 | 346.0 | 346.0 | 41.0 |

# DAP (R–PDSO–G**) PowerPAD™ PLASTIC SMALL–OUTLINE PACKAGE

38 PINS SHOWN




| DIM \ PINS ** | 28 | 30 | 32 | 38 |
|---|---|---|---|---|
| A MAX | 9,80 | 11,10 | 11,10 | 12,60 |
| A MIN | 9,60 | 10,90 | 10,90 | 12,40 |

4073257/C 11/05

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <http://www.ti.com>.
E. Falls within JEDEC MO–153

**PowerPAD is a trademark of Texas Instruments.**

# THERMAL PAD MECHANICAL DATA

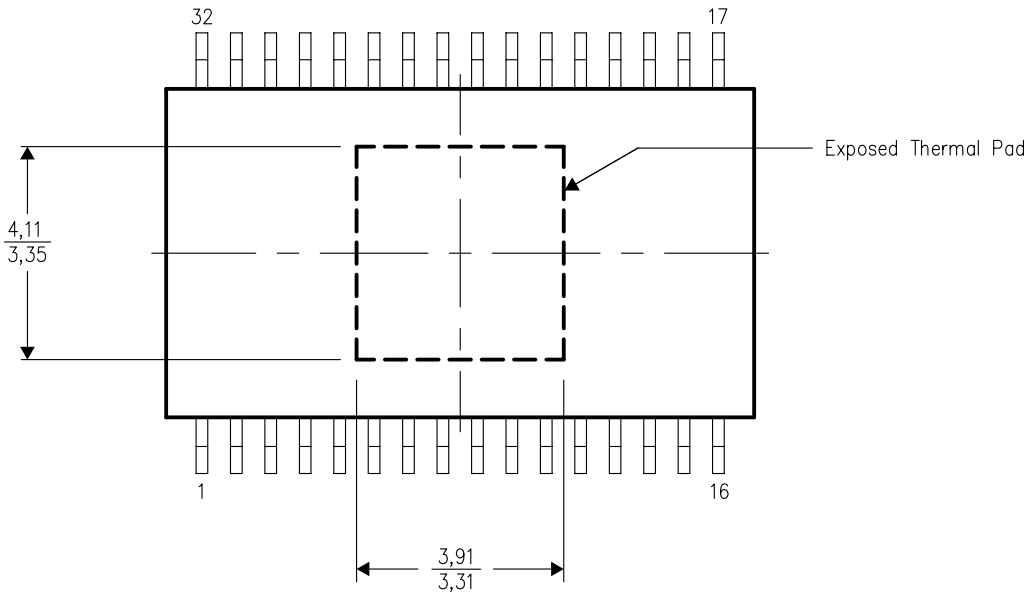
## DAP (R–PDSO–G32)

### THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No–Lead (QFN) package and its advantages, refer to Application Report, Quad Flatpack No–Lead Logic Packages, Texas Instruments Literature No. SCBA017. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.




Top View

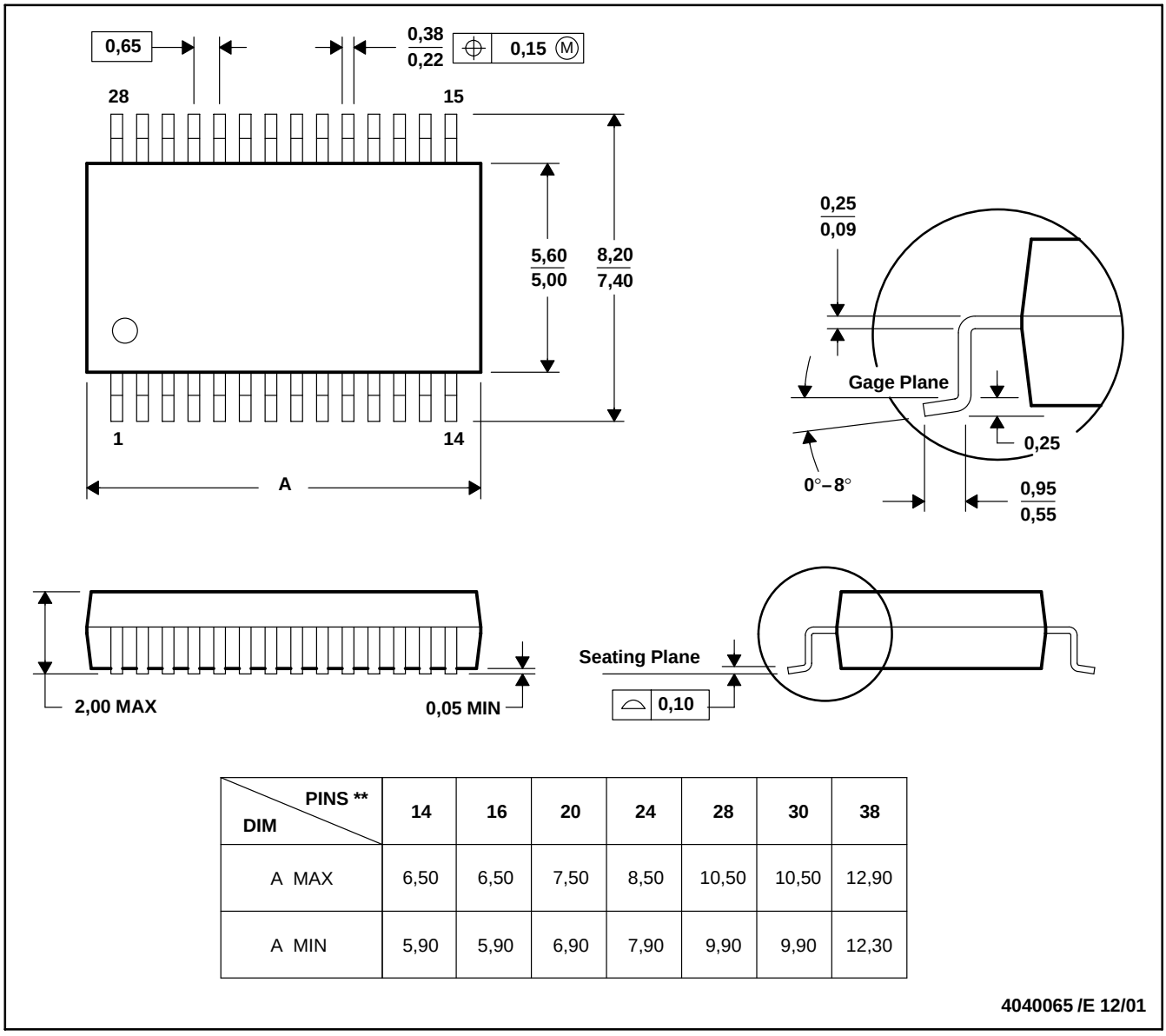
NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

MSSO002E – JANUARY 1995 – REVISED DECEMBER 2001

**DB (R-PDSO-G**)** **PLASTIC SMALL-OUTLINE**

**28 PINS SHOWN**




| DIM \ PINS ** | 14 | 16 | 20 | 24 | 28 | 30 | 38 |
|---|---|---|---|---|---|---|---|
| A MAX | 6,50 | 6,50 | 7,50 | 8,50 | 10,50 | 10,50 | 12,90 |
| A MIN | 5,90 | 5,90 | 6,90 | 7,90 | 9,90 | 9,90 | 12,30 |

**4040065 /E 12/01**

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

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